

SX-A Family FPGAs

Leading Edge Performance

- 250 MHz System Performance
- 4ns Clock-to-Out (Pin-to-Pin)
- 330 MHz Internal Performance

Specifications

- 12,000 to 108,000 Available System Gates
- Up to 360 User-Programmable I/O Pins
- Up to 4,024 Flip-Flops
- 0.25 μ CMOS Process Technology

Features

- I/Os with Live or "Hot-Swapping" Capability
- Power Up/Down Friendly (No Sequencing Required for Supply Voltages)
- 66 MHz PCI Compliant
- CPLD and FPGA Integration
- Single Chip Solution

- Configurable I/O Support for 3.3V/5.0V PCI, LVTTIL, and TTL
- Configurable Weak Resistor Pullup or Pulldown for Tri-Stated Outputs at Power Up
- 100% Resource Utilization with 100% Pin Locking
- 2.5V, 3.3V, and 5.0V Mixed Voltage Operation with 5.0V Input Tolerance and 5.0V Drive Strength
- Very Low Power Consumption
- Deterministic, User-Controllable Timing
- Unique In-System Diagnostic and Verification Capability with Silicon Explorer II
- JTAG Boundary Scan Testing in Compliance with IEEE Standard 1149.1
- Actel Designer Series Design Tools, Supported by VeriBest, Cadence, Exemplar, IST, Mentor Graphics, Model Technology, Synopsys, Synplicity, and Viewlogic Design Entry and Simulation Tools
- Secure Programming Technology Prevents Reverse Engineering and Design Theft

SX-A Product Profile

	A54SX08A	A54SX16A	A54SX32A	A54SX72A
Typical Gates	8,000	16,000	32,000	72,000
System Gates	12,000	24,000	48,000	108,000
Logic Modules	768	1,452	2,880	6,036
Combinatorial Cells	512	924	1,800	4,024
Register Cells (Dedicated Flip-Flops)	256	528	1,080	2,012
Maximum Flip-Flops	512	990	1,980	4,024
Maximum User I/Os	130	177	249	360
Clocks	3	3	3	3
Quadrant Clocks	0	0	0	4
JTAG Boundary Scan Testing	Yes	Yes	Yes	Yes
3.3V/5.0V PCI	Yes	Yes	Yes	Yes
Clock-to-Out	TBD	TBD	4.5 ns	4.8 ns
Input Set-Up (External)	TBD	TBD	-1.3 ns	-3.3 ns
Speed Grades	Std, -1, -2, -3	Std, -1, -2, -3	Std, -1, -2, -3	Std, -1, -2, -3
Temperature Grades	C, I, M	C, I, M	C, I, M	C, I, M
Package (by pin count)				
PQFP	208	208	208	208
TQFP	100, 144	100, 144	144	—
PBGA	—	—	329	—
FBGA	144	144	144, 256	484

General Description

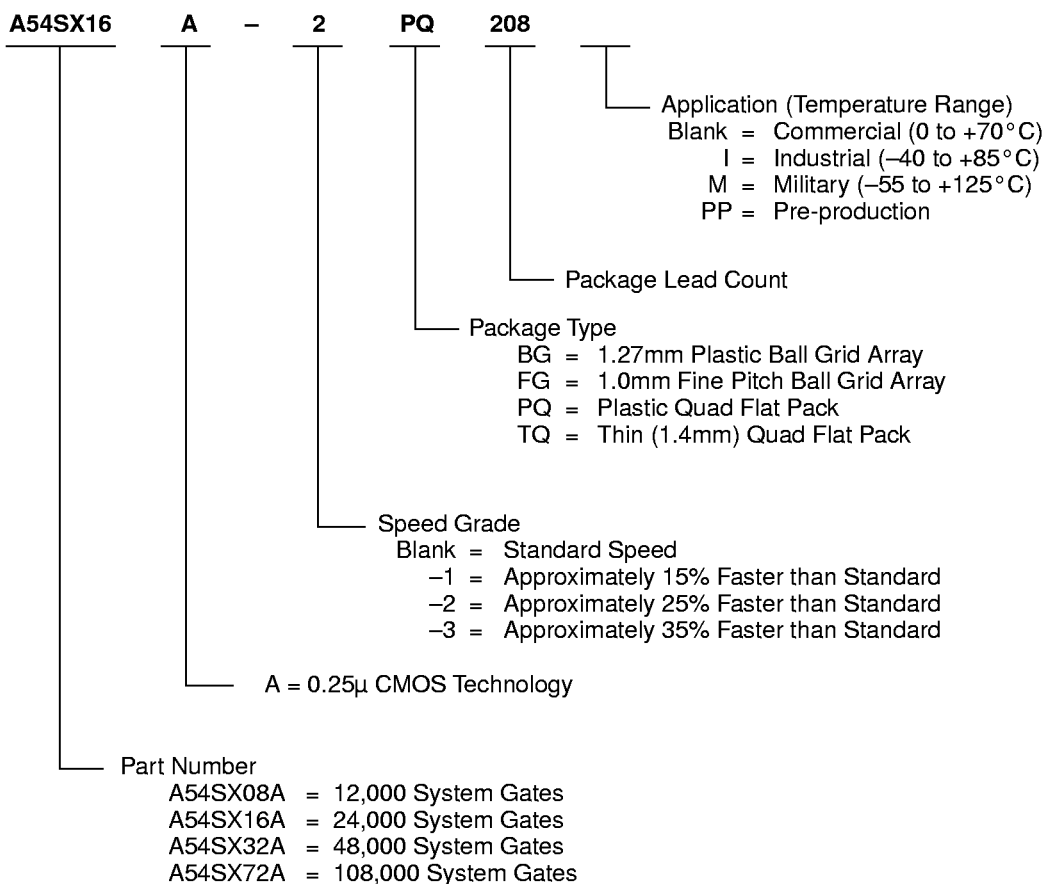
Actel's SX-A family of FPGAs features a sea-of-modules architecture that delivers next-generation device performance and integration levels not currently achieved by any other FPGA architecture. SX-A devices greatly simplify design time, enable dramatic reductions in design costs and power consumption, and further speed time-to-market for performance-intensive applications.

Actel's SX-A architecture features two types of logic modules, the combinatorial cell (C-cell) and the register cell (R-cell), each optimized for fast and efficient mapping of synthesized logic functions. The routing and interconnect resources are located in the metal layers above the logic modules, providing optimal use of silicon. This enables the entire floor of the device to be spanned with an uninterrupted grid of fine-grained, synthesis-friendly logic modules (or "sea-of-modules"), which reduces the distance signals have to travel between logic modules. To minimize signal propagation delay, SX-A devices employ both local and general routing resources. The high-speed local routing resources (DirectConnect and FastConnect) enable very fast local

signal propagation that is optimal for fast counters, state machines, and datapath logic. The general system of segmented routing tracks allows any logic module in the array to be connected to any other logic or I/O module. Within this system, propagation delay is minimized by limiting the number of antifuse interconnect elements to five (90% of connections typically use only three antifuses). The unique local and general routing structure featured in SX-A devices gives fast and predictable performance, allows 100% pin-locking with full logic utilization, enables concurrent PCB development, reduces design time, and allows designers to achieve performance goals with a minimum of effort.

Further complementing SX-A's flexible routing structure is a hard-wired, constantly-loaded clock network that has been tuned to provide fast clock propagation with minimal clock skew. Additionally, the high performance of the internal logic has eliminated the need to embed latches or flip-flops in the I/O cells to achieve fast clock-to-out or fast input set-up times. SX-A devices have easy-to-use I/O cells that do not require HDL instantiation, facilitating design re-use and reducing design and verification time.

Ordering Information



Product Plan

	Speed Grade*				Application		
	Std	-1	-2	-3	C	I†	M*
A54SX08A Device							
100-Pin Thin Quad Flat Pack (TQFP)	P	P	P	P	P	P	P
144-Pin Thin Quad Flat Pack (TQFP)	P	P	P	P	P	P	P
208-Pin Plastic Quad Flat Pack (PQFP)	P	P	P	P	P	P	P
144-Pin Fine Pitch Ball Grid Array (FBGA)	P	P	P	P	P	P	P
A54SX16A Device							
100-Pin Thin Quad Flat Pack (TQFP)	P	P	P	P	P	P	P
144-Pin Thin Quad Flat Pack (TQFP)	P	P	P	P	P	P	P
208-Pin Plastic Quad Flat Pack (PQFP)	P	P	P	P	P	P	P
144-Pin Fine Pitch Ball Grid Array (FBGA)	P	P	P	P	P	P	P
256-Pin Fine Pitch Ball Grid Array (FBGA)	P	P	P	P	P	P	P
A54SX32A Device							
144-Pin Thin Quad Flat Pack (TQFP)	P	P	P	P	P	P	P
208-Pin Plastic Quad Flat Pack (PQFP)	✓	✓	✓	✓	✓	P	P
144-Pin Fine Pitch Ball Grid Array (FBGA)	P	P	P	P	P	P	P
256-Pin Fine Pitch Ball Grid Array (FBGA)	P	P	P	P	P	P	P
329-Pin Plastic Ball Grid Array (PBGA)	✓	✓	✓	✓	✓	P	P
A54SX72A Device							
208-Pin Plastic Quad Flat Pack (PQFP)	P	P	P	P	P	P	P
484-Pin Fine Pitch Ball Grid Array (FBGA)	P	P	P	P	P	P	P

Contact your Actel sales representative for product availability.

Applications: C = Commercial Availability: ✓ = Available
 I = Industrial P = Planned
 M = Military — = Not Planned

*Speed Grade: -1 = Approx. 15% faster than Standard
 -2 = Approx. 25% faster than Standard
 -3 = Approx. 35% faster than Standard

† Only Std, -1, -2 Speed Grade

• Only Std, -1 Speed Grade

Plastic Device Resources

Device	User I/Os (including clock buffers)						
	PQFP 208-Pin	TQFP 100-Pin	TQFP 144-Pin	FBGA 144-Pin	FBGA 256-Pin	PBGA 329-Pin	FBGA 484-Pin
A54SX08A	130	81	113	TBD	—	—	—
A54SX16A	175	81	113	TBD	—	—	—
A54SX32A	174	—	113	TBD	TBD	249	—
A54SX72A	171	—	—	—	—	—	360

Contact your Actel sales representative for product availability.

Package Definitions

PQFP = Plastic Quad Flat Pack, TQFP = Thin Quad Flat Pack, PBGA = 1.27mm Plastic Ball Grid Array, FBGA = 1.0mm Fine Pitch Ball Grid Array.

Pin Description

CLKA/B Clock A and B

3.3V/5.0VPCI/TTL clock input for clock distribution networks. The clock input is buffered prior to clocking the R-cells. If not used, this pin must be set LOW or HIGH on the board. It must not be left floating.

QCLKA/B/C/D Quadrant Clock A, B, C, and D

These four pins are the quadrant clock inputs. They are 3.3V/5.0VPCI/TTL clock input for clock distribution networks. Each of these clock inputs can drive up to a quarter of the chip, and they can be grouped together to drive multiple quadrants. The clock input is buffered prior to clocking the R-cells. If not used, this pin must be set LOW or HIGH on the board. It must not be left floating. (These quadrant clocks are only for 54SX72A).

TCK Test Clock

Test clock input for diagnostic probe and device programming. In flexible mode (refer to Table 2, "JTAG Pins Functionality," on page 10), TCK becomes active when the TMS pin is set LOW. This pin functions as an I/O when the JTAG state machine reaches the "logic reset" state.

GND Ground

LOW supply voltage.

HCLK Dedicated (Hard-wired) Array Clock

TTL/3.3VPCI clock input for sequential modules. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. If not used, this pin must be set LOW or HIGH on the board. It must not be left floating.

I/O Input/Output

The I/O pin functions as an input, output, three-state, or bi-directional buffer. Based on certain configurations, input and output levels are compatible with standard TTL, LVTTTL, 3.3V PCI or 5.0V PCI specifications. Unused I/O pins are tri-stated by the Designer Series software.

TMS Test Mode Select

The TMS pin controls the use of JTAG pins (TCK, TDI, TDO). In flexible mode (refer to Table 2, "JTAG Pins Functionality," on page 10), when the TMS pin is set LOW, the TCK, TDI, and TDO pins are JTAG pins. Once the JTAG pins are in JTAG mode they will remain in JTAG mode until the internal JTAG

state machine reaches the "logic reset" state. At this point the JTAG pins will be released and will function as regular I/O pins. The "logic reset" state is reached 5 TCK cycles after the TMS pin is set HIGH. In dedicated JTAG mode, TMS functions as specified in the IEEE 499.1 JTAG Specifications. JTAG operation is further described on page 10.

NC No Connection

This pin is not connected to circuitry within the device.

PRA Probe A

The Probe A pin is used to output data from any user-defined design node within the device. This independent diagnostic pin can be used in conjunction with the Probe B pin to allow real-time diagnostic output of any signal path within the device. The Probe A pin can be used as a user-defined I/O when debugging has been completed.

PRB Probe B

The Probe B pin is used to output data from any node within the device. This diagnostic pin can be used in conjunction with the Probe A pin to allow real-time diagnostic output of any signal path within the device. The Probe B pin can be used as a user-defined I/O when debugging has been completed.

TDI Test Data Input

Serial input for JTAG and diagnostic probe. In flexible mode, (refer to Table 2, "JTAG Pins Functionality," on page 10), TDI is active when the TMS pin is set LOW. This pin functions as an I/O when the JTAG state machine reaches the "logic reset" state.

TDO Test Data Output

Serial output for JTAG. In flexible mode (refer to Table 2, "JTAG Pins Functionality," on page 10), TDO is active when the TMS pin is set LOW. This pin functions as an I/O when the JTAG state machine reaches the "logic reset" state.

VCCI Supply Voltage

Supply voltage for I/Os.

VCCA Supply Voltage

Supply voltage for Array.

TRST JTAG Reset Pin

Active-low input to asynchronously initialize or reset the JTAG circuit.

Table 1 • Supply Voltages

	V _{CCA}	V _{CCI}	Maximum Input Tolerance	Maximum Output Drive
A54SX08A	2.5V	2.5V	5.0V	2.5V
A54SX16A	2.5V	3.3V	5.0V	3.3V
A54SX32A	2.5V	5.0V	5.0V	5.0V
A54SX72A	2.5V	5.0V	5.0V	5.0V

SX-A Family Architecture

The SX-A family architecture was designed to satisfy next-generation performance and integration requirements for production-volume designs in a broad range of applications.

Programmable Interconnect Element

The SX-A family provides much more efficient use of silicon by locating the routing interconnect resources between the Metal 2 (M2) and Metal 3 (M3) layers (see Figure 1). This completely eliminates the channels of routing and interconnect resources between logic modules (as implemented on SRAM FPGAs and previous generations of antifuse FPGAs), and enables the entire floor of the device to be spanned with an uninterrupted grid of logic modules.

Interconnection between these logic modules is achieved using Actel's patented metal-to-metal programmable antifuse

interconnect elements, which are embedded between the M2 and M3 layers. The antifuses are normally open circuit and, when programmed, form a permanent low-impedance connection.

The extremely small size of these interconnect elements gives the SX-A family abundant routing resources and provides excellent protection against design pirating. Reverse engineering is virtually impossible because it is extremely difficult to distinguish between programmed and unprogrammed antifuses, and there is no configuration bitstream to intercept.

Additionally, the interconnect (i.e., the antifuses and metal tracks) have lower capacitance and lower resistance than any other device of similar capacity, leading to the fastest signal propagation in the industry.

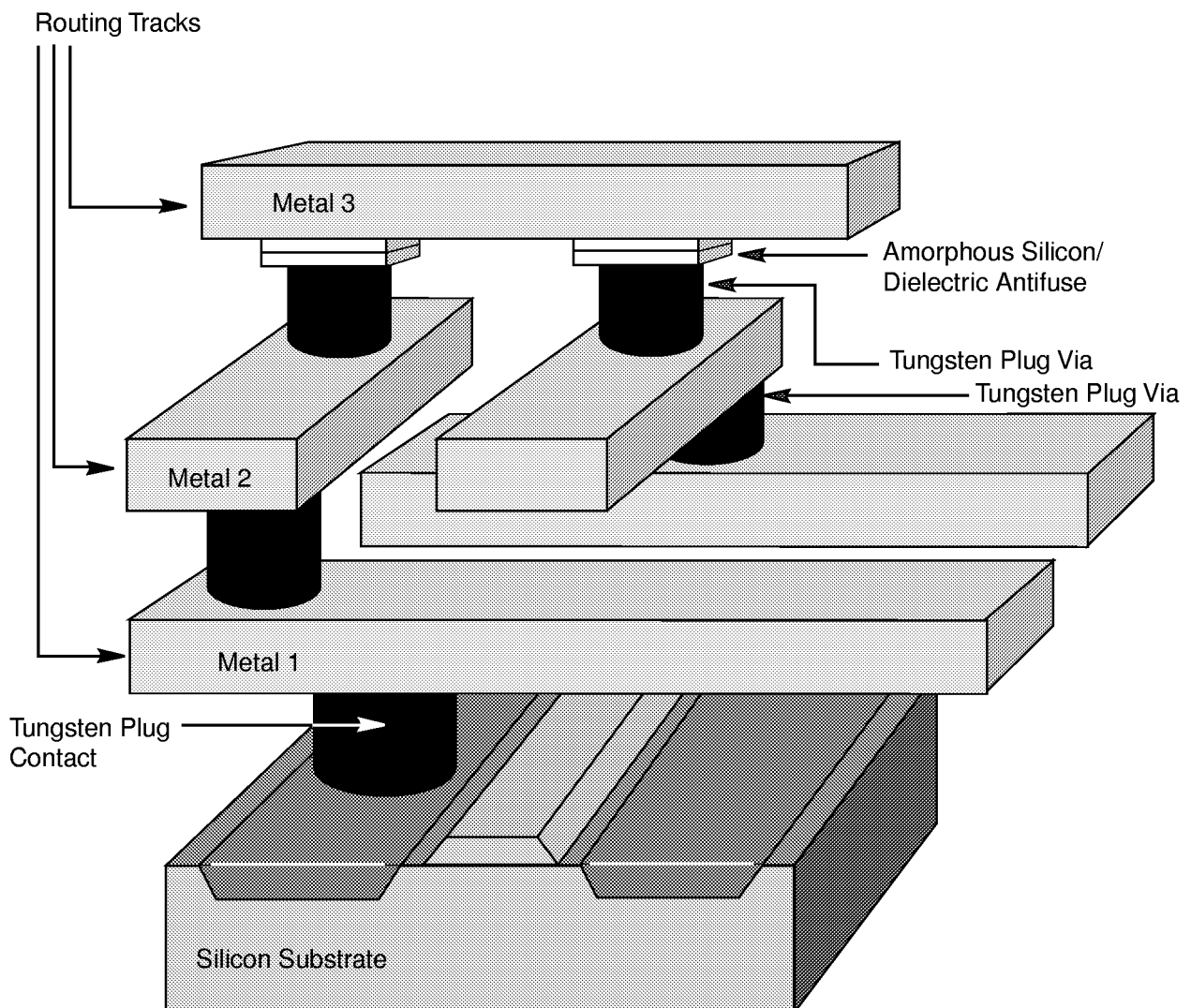


Figure 1 • SX-A Family Interconnect Elements

Logic Module Design

The SX-A family architecture has been called a “sea-of-modules” architecture because the entire floor of the device is covered with a grid of logic modules with virtually no

chip area lost to interconnect elements or routing (see Figure 2). Actel provides two types of logic modules, the R-cell and the C-cell.

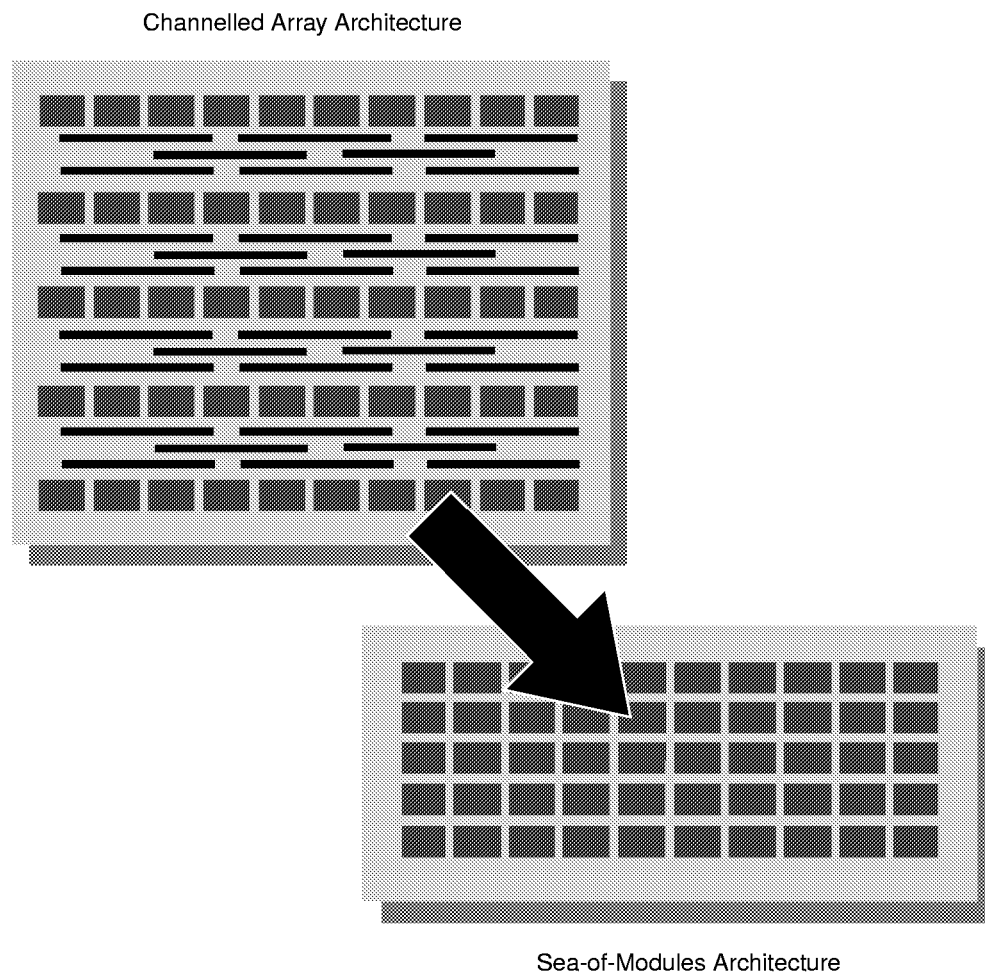


Figure 2 • Channelled Array and Sea-of-Modules Architectures

The R-cell (or register cell) contains a flip-flop featuring asynchronous clear, asynchronous preset, and clock enable (using the S0 and S1 lines) control signals. The R-cell (Figure 3 on page 7) registers feature programmable clock polarity, selectable on a register-by-register basis. This provides the designer with additional flexibility while allowing mapping of synthesized functions into the SX-A FPGA. The clock source for the R-cell can be chosen from the hard-wired clock or the routed clock.

The C-cell (or combinatorial cell, Figure 4 on page 7) implements a range of combinatorial functions up to 5-inputs. Inclusion of the DB input and its associated inverter function dramatically increases the number of combinatorial functions that can be implemented in a single module from 800 options

in previous architectures to more than 4,000 in the SX-A architecture. An example of the improved flexibility enabled by the inversion capability is the ability to integrate a 3-input exclusive-OR function into a single C-cell. This facilitates construction of 9-bit parity-tree functions with 2 ns propagation delays. At the same time, the C-cell structure is extremely synthesis-friendly, simplifying the overall design and reducing synthesis time.

Chip Architecture

The SX-A family's chip architecture provides a unique approach to module organization and chip routing that delivers the best register/logic mix for a wide variety of new and emerging applications.

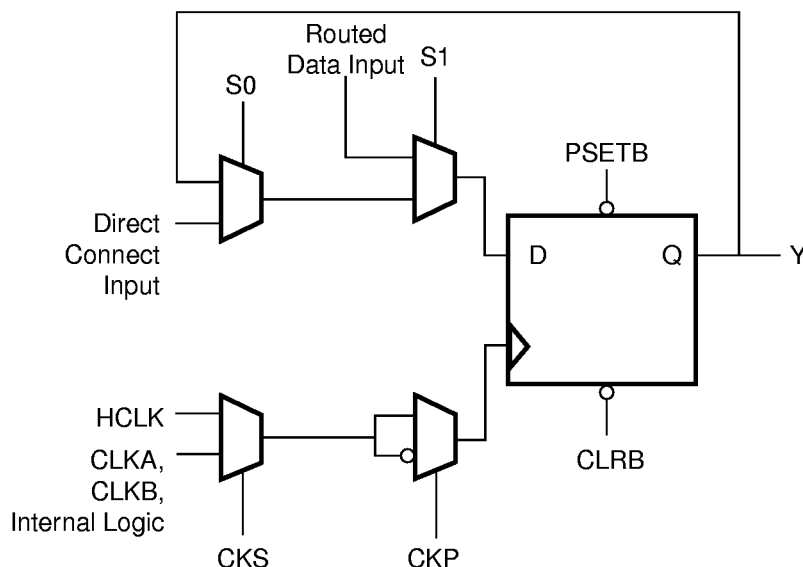


Figure 3 • R-Cell

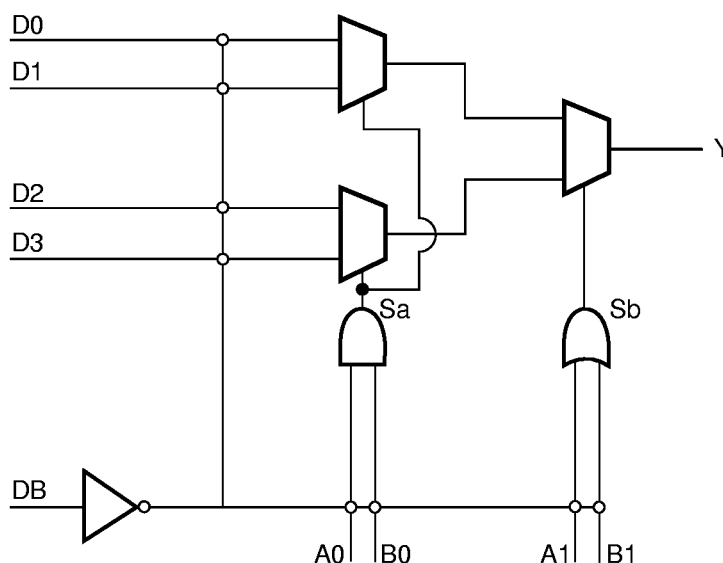


Figure 4 • C-Cell

Module Organization

Actel has arranged all C-cell and R-cell logic modules into horizontal banks called *Clusters*. There are two types of Clusters: Type 1 contains two C-cells and one R-cell, while Type 2 contains one C-cell and two R-cells.

To increase design efficiency and device performance, Actel has further organized these modules into *SuperClusters* (see Figure 5 on page 8). SuperCluster 1 is a two-wide grouping of Type 1 clusters. SuperCluster 2 is a two-wide group containing one Type 1 cluster and one Type 2 cluster. SX-A devices feature significantly more SuperCluster 1 modules than

SuperCluster 2 modules because designers typically require significantly more combinatorial logic than flip-flops.

Routing Resources

Clusters and SuperClusters can be connected through the use of two innovative new local routing resources called *FastConnect* and *DirectConnect* which enable extremely fast and predictable interconnection of modules within Clusters and SuperClusters (see Figure 6 on page 8 and Figure 7 on page 9). This routing architecture also dramatically reduces the number of antifuses required to complete a circuit, ensuring the highest possible performance.

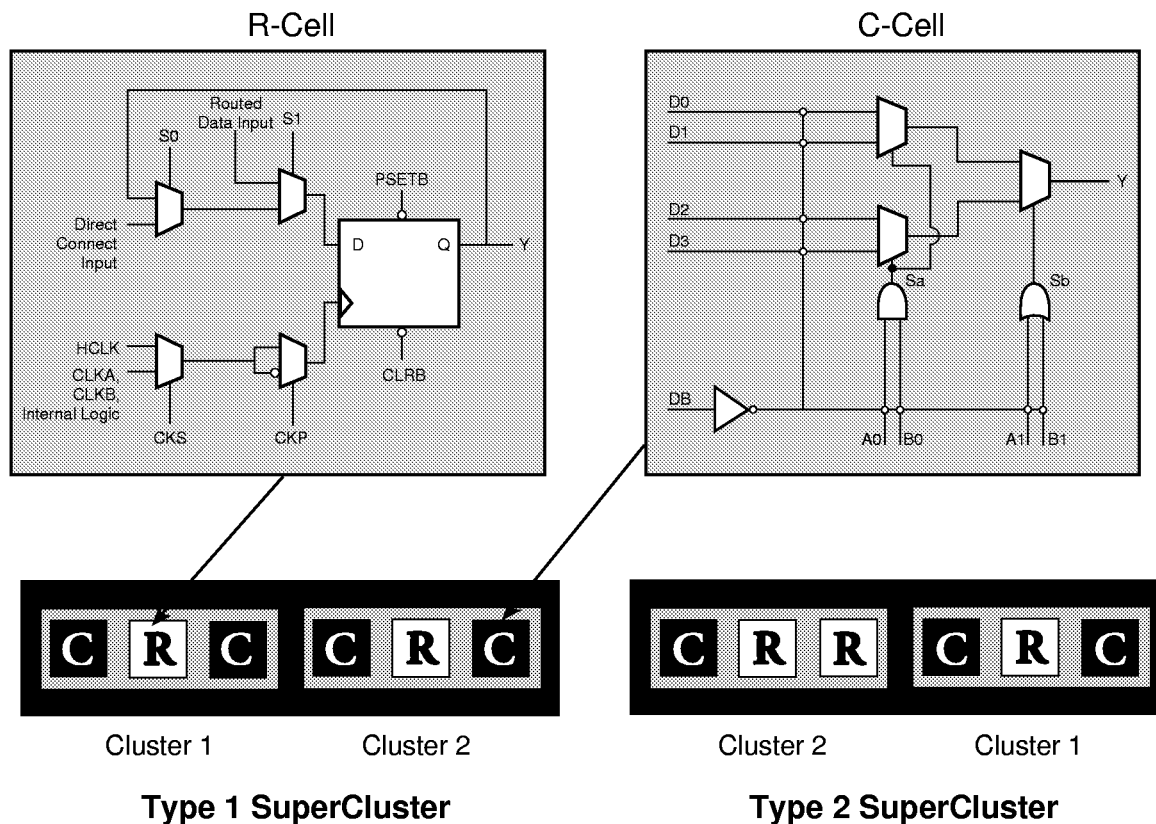


Figure 5 • Cluster Organization

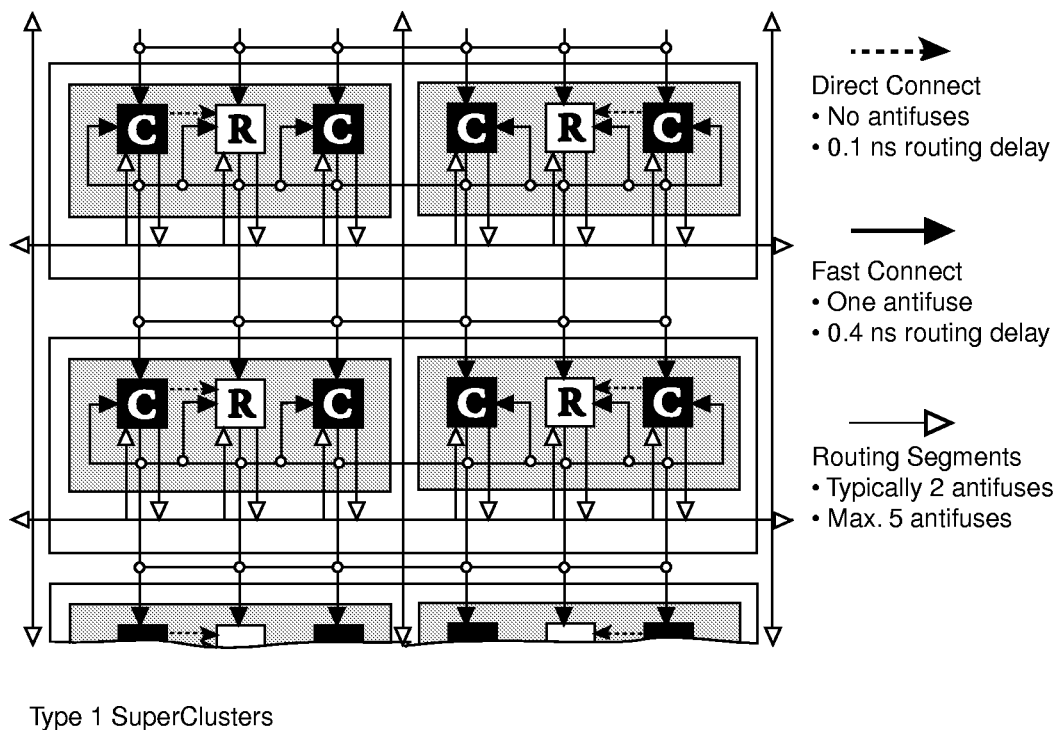


Figure 6 • DirectConnect and FastConnect for Type 1 SuperClusters

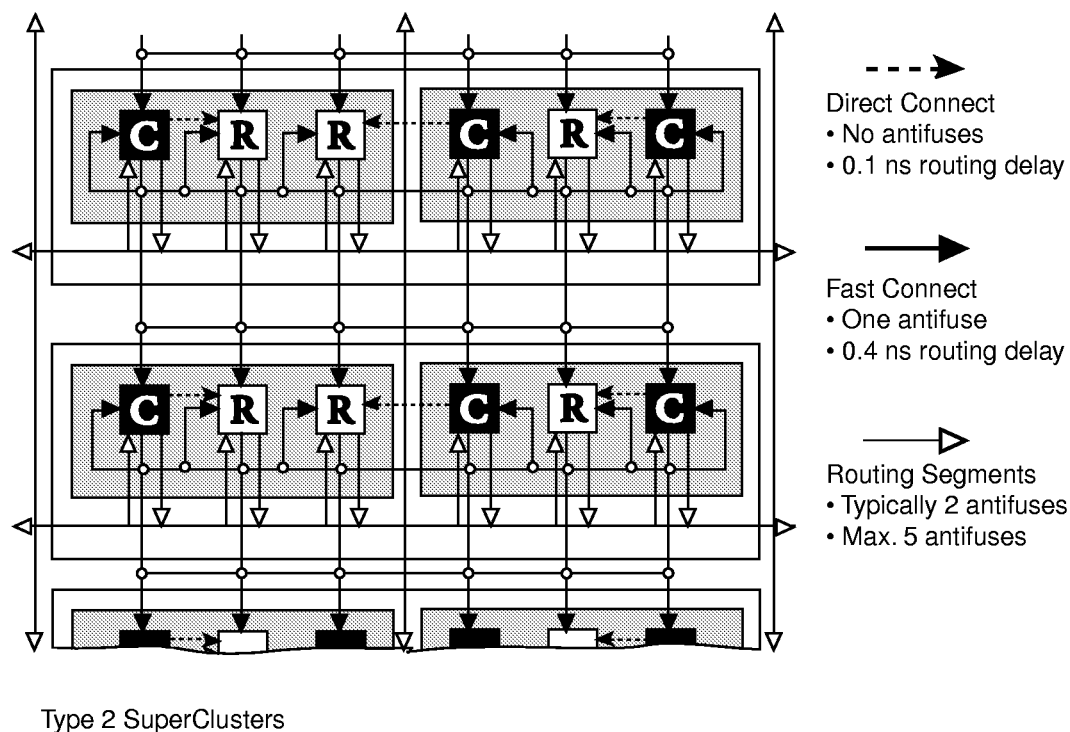


Figure 7 • DirectConnect and FastConnect for Type 2 SuperClusters

DirectConnect is a horizontal routing resource that provides connections from a C-cell to its neighboring R-cell in a given SuperCluster. DirectConnect uses a hard-wired signal path requiring no programmable interconnection to achieve its fast signal propagation time of less than 0.1 ns.

FastConnect enables horizontal routing between any two logic modules within a given SuperCluster, and vertical routing with the SuperCluster immediately below it. Only one programmable connection is used in a FastConnect path, delivering maximum pin-to-pin propagation of 0.2 ns.

In addition to DirectConnect and FastConnect, the architecture makes use of two globally-oriented routing resources known as segmented routing and high-drive routing. Actel's segmented routing structure provides a variety of track lengths for extremely fast routing between SuperClusters. The exact combination of track lengths and antifuses within each path is chosen by the 100% automatic place and route software to minimize signal propagation delays.

Actel's high-drive routing structure provides three clock networks. The first clock, called HCLK, is hard-wired from the HCLK buffer to the clock select MUX in each R-cell. This provides a fast propagation path for the clock signal, enabling the 4.0 ns clock-to-out (pin-to-pin) performance of the SX-A devices. The hard-wired clock is tuned to provide clock skew as low as 0.25 ns. The remaining two clocks (CLKA, CLKB)

are global clocks that can be sourced from external pins or from internal logic signals within the SX-A device.

In addition, the SX72A device provides four quadrant clocks (QCLKA, QCLKB, QCLKC, QCLKD). These clocks can be sourced from external pins or from internal logic signals within the SX72A device. Each of these clocks can individually drive up to a quarter of the chip, or they can be grouped together to drive multiple quadrants.

Other Architecture Features

Technology

Actel's SX-A family is implemented in high-voltage twin-well CMOS using three layers of metal and 0.25 μ design rules (moving quickly to 0.22 μ). The M2/MB antifuse is made up of a combination of amorphous silicon and dielectric material with barrier metals, and has a programmed ("on" state) resistance of 25 ohms with capacitance of 1.0 fF for low signal impedance.

Performance

The combination of architectural features described above enables SX-A devices to operate with internal clock frequencies exceeding 300 MHz, enabling very fast execution of even complex logic functions. Thus, the SX-A family is an optimal platform upon which to integrate the functionality previously contained in multiple CPLDs. In addition, designs that previously would have required a gate array to meet

performance goals can now be integrated into an SX-A device with dramatic improvements in cost and time-to-market. Using timing-driven place and route tools, designers can achieve highly deterministic device performance.

With SX-A devices, designers can achieve a higher level of performance without recourse to complicated performance-enhancing design techniques such as the use of redundant logic to reduce fanout on critical nets or the instantiation of macros in HDL code.

I/O Modules

Each I/O on an SX-A device can be configured as an input, an output, a tri-state output, or a bi-directional pin. Even without the inclusion of dedicated I/O registers, these I/Os, in combination with array registers, can achieve clock-to-out (pad-to-pad) timing as fast as 4.0 ns. I/O cells including embedded latches and flip-flops require instantiation in HDL code, a design complication not required by SX-A FPGAs. Fast pin-to-pin timing ensures that the device will have little trouble interfacing with any other device in the system, which in turn enables parallel design of system components and reducing overall design time.

Hot Swapping

SX-A I/Os are specifically designed to be programmed to be hot swappable. During power up/down (or partial up/down), all I/Os are tri-stated. V_{CCA} and V_{CC1} do not have to be stable during power up/down and they are not required to power up or power down in any particular sequence in order to avoid damage to the SX-A devices. After the SX-A device is plugged in to an electrically active system, the device will not degrade the reliability of or cause damage to the host-system. The devices' output pins are driven to a high impedance state until normal chip operating conditions are reached.

Power Requirements

The SX-A family supports 2.5V/3.3V/5.0V mixed voltage operation and is designed to tolerate 5-volt inputs in each case. Power consumption is extremely low due to the very short distances signals are required to travel to complete a circuit. Power requirements are further reduced due to the small number of antifuses in the path, and because of the low resistance properties of the antifuses. The antifuse architecture does not require active circuitry to hold a charge (as do SRAM or EPROM), making it the lowest-power architecture on the market.

JTAG

All SX-A devices are IEEE 1149.1 (JTAG) compliant. SX-A devices offer superior diagnostic and testing capabilities by providing JTAG and probing capabilities. These functions are controlled through the special JTAG pins in conjunction with the program fuse. The functionality of each pin is described in Table 2.

Table 2 • JTAG Pins Functionality

Program Fuse Blown (Dedicated JTAG Mode)	Program Fuse Not Blown (Flexible Mode)
TCK, TDI, TDO are dedicated JTAG pins	TCK, TDI, TDO are flexible and may be used as I/Os
No need for pull-up resistor for TMS	Use a pull-up resistor of 10K ohm on TMS

In the dedicated JTAG mode, TCK, TDI and TDO are dedicated JTAG pins and cannot be used as regular I/Os. In flexible mode, TMS should be set HIGH through a pull-up resistor of 10K ohm. TMS can be pulled LOW to initiate the JTAG sequence.

The program fuse determines whether the device is in dedicated or flexible mode. The default (fuse not blown) is flexible mode.

Design Tool Support

As with all Actel FPGAs, the SX-A family is fully supported by Actel's Designer Series and DeskTOP development tools, which include:

- DirectTime for automated, timing-driven place and route;
- ACTgen for fast development using a wide range of macro functions; and

Designer Series supports industry-leading VHDL and Verilog-based design tools, including synthesis tools from industry leaders such as Exemplar Logic, Synplicity, and Synopsys.

Silicon Explorer and SX-A FPGAs

Actel SX-A FPGAs include internal Probe circuitry to dynamically observe and analyze any signal inside the FPGA during normal device operation. The Probe circuitry is accessed and controlled by Silicon Explorer II, an integrated verification and logic analysis tool that attaches to a PC. Silicon Explorer II is also an 18-channel logic analyzer that samples data at 100 MHz (asynchronous) or 66 MHz (synchronous). Two channels of the logic analyzer have a direct connection to PRA and PRB pins, which can automatically display any two signals inside the FPGA. The remaining 16 channels of the logic analyzer can be used to examine other signals on the board. In addition, Silicon Explorer II can read back the design's checksum, allowing designers to verify that the correct design was programmed in the FPGA.

SX-A Probe Circuit Control Pins

The Silicon Explorer II tool uses the JTAG ports (TDI, TCK, TMS and TDO) to select the desired nets for debugging. The selected internal nets are assigned to the PRA/PRB pins for observation. Figure 8 illustrates the interconnection between Silicon Explorer II and the FPGA to perform in-circuit debugging.

Design Considerations

Avoid using the TDI, TCK, TDO, PRA and PRB pins as input or bi-directional ports. Because these pins are active during probing, critical signal input through these pins is not available while probing. In addition, do not program the Security Fuse. Programming the Security Fuse disables the Probe Circuitry.

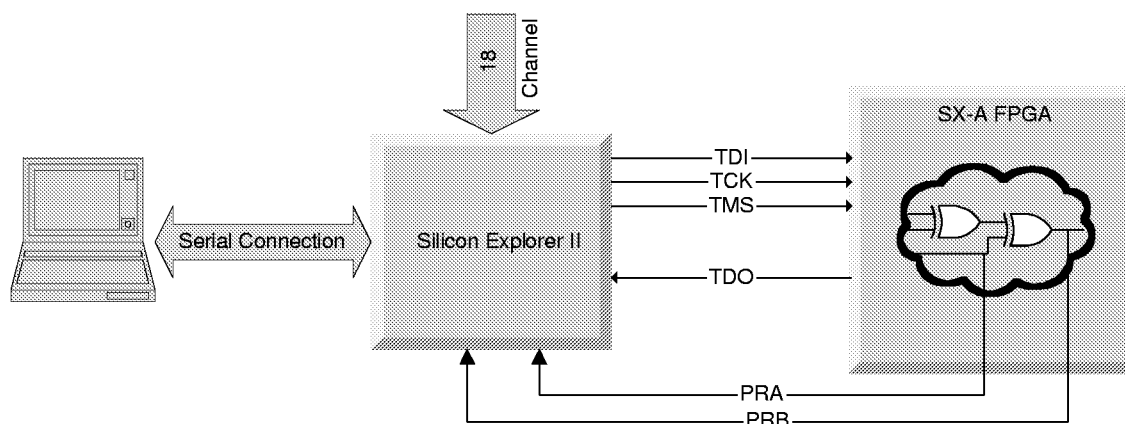


Figure 8 • Probe Setup

2.5V/3.3V/5.0V Operating Conditions

Absolute Maximum Ratings¹

Symbol	Parameter	Limits	Units
V _{CCI}	DC Supply Voltage	−0.3 to +6.0	V
V _{CCA}	DC Supply Voltage	−0.3 to +3.0	V
V _I	Input Voltage	−0.5 to +5.5	V
V _O	Output Voltage	−0.5 to +V _{CCI} + 0.5	V
I _{IO}	I/O Source Sink Current ²	−30 to +5.0	mA
T _{STG}	Storage Temperature	−65 to +150	°C

Notes:

- Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. Exposure to absolute maximum rated conditions for extended periods may affect device reliability. Device should not be operated outside the Recommended Operating Conditions.
- The I/O source sink numbers refer to tri-stated inputs and outputs.

Recommended Operating Conditions

Parameter	Commercial	Industrial	Military	Units
Temperature Range ¹	0 to +70	−40 to +85	−55 to +125	°C
3.3V Power Supply Tolerance	±10	±10	±10	%V _{CC}
5V Power Supply Tolerance	±5	±10	±10	%V _{CC}
2.5V Power Supply Tolerance	±8	±8	±8	%V _{CC}

Note:

- Ambient temperature (T_A) is used for commercial and industrial; case temperature (T_C) is used for military.

Electrical Specifications

Symbol Parameter		Commercial		Industrial		Units
		Min.	Max.	Min.	Max.	
V_{OH}	($I_{OH} = -20\mu A$) (CMOS) ($I_{OH} = -8mA$) (TTL) ($I_{OH} = -6mA$) (TTL)	($V_{CCI} - 0.1$) 2.4	V_{CCI} V_{CCI}	($V_{CCI} - 0.1$) 2.4	V_{CCI} V_{CCI}	V
V_{OL}	($I_{OL} = 20\mu A$) (CMOS) ($I_{OL} = 12mA$) (TTL) ($I_{OL} = 8mA$) (TTL)		0.10 0.50		0.50	V
V_{IL}			0.8		0.8	V
V_{IH}		2.0		2.0		V
I_{IL}	Input Leakage Current, $V_{IN} = V_{CCI}$ or GND	-10	10	-10	10	μA
I_{OZ}	3-State Output Leakage Current, $V_{OUT} = V_{CCI}$ or GND	-10	10	-10	10	μA
t_R, t_F	Input Transition Time t_R, t_F		10		10	ns
C_{IO}	C_{IO} I/O Capacitance		10		10	pF
I_{CC}	Standby Current, I_{CC}		10		20	mA

PCI Compliance for the SX-A Family

The SX-A family supports 3.3V and 5V PCI and is compliant with the PCI Local Bus Specification Rev. 2.1.

DC Specifications (5.0V PCI Operation)

Symbol	Parameter	Condition	Min.	Max.	Units
V_{CCA}	Supply Voltage for Array		2.3	2.7	V
V_{CCI}	Supply Voltage for IOs		4.75	5.25	V
V_{IH}	Input High Voltage ¹		2.0	$V_{CCI} + 0.5$	V
V_{IL}	Input Low Voltage ¹		-0.5	0.8	V
I_{IH}	Input High Leakage Current	$V_{IN} = 2.7$		70	μA
I_{IL}	Input Low Leakage Current	$V_{IN} = 0.5$		-70	μA
V_{OH}	Output High Voltage	$I_{OUT} = -2 mA$	2.4		V
V_{OL}	Output Low Voltage ²	$I_{OUT} = 3 mA, 6 mA$		0.55	V
C_{IN}	Input Pin Capacitance ³			10	pF
C_{CLK}	CLK Pin Capacitance		5	12	pF

Notes:

- Input leakage currents include hi-Z output leakage for all bi-directional buffers with tri-state outputs.
- Signals without pull-up resistors must have 3 mA low output current. Signals requiring pull up must have 6 mA; the latter include, FRAME#, IRDY#, IRDY#, DEVSEL#, STOP#, SERR#, PERR#, LOCK#, and, when used AD[63::32], CBE[7:4]#, PAR64, REQ64#, and ACK64#.
- Absolute maximum pin capacitance for a PCI input is 10 pF (except for CLK) with an exception granted to motherboard-only devices, which could be up to 16 pF, in order to accommodate PGA packaging. This would mean, in general, that components for expansion boards would need to use alternatives to ceramic PGA packaging (i.e., PQFP, SGA, etc.).

AC Specifications (5.0V PCI Operation)

Symbol	Parameter	Condition	Min.	Max.	Units
$I_{OH(AC)}$	Switching ¹	$0 < V_{OUT} \leq 1.4$	-44		mA
	Current High ^{1, 2}	$1.4 \leq V_{OUT} < 2.4$	$(-44 + (V_{OUT} - 1.4)/0.024)$		mA
	1, 3	$3.1 < V_{OUT} < V_{CCI}$		Eq. A	
	(Test Point) ³	$V_{OUT} = 3.1$		-142	mA
$I_{OL(AC)}$	Switching ¹	$V_{OUT} \geq 2.2$	95		mA
	Current Low ¹	$2.2 > V_{OUT} > 0.55$	$(V_{OUT}/0.023)$		mA
	1, 3	$0.71 > V_{OUT} > 0$		Eq. B	
	(Test Point) ³	$V_{OUT} = 0.71$		206	mA
I_{CL}	Low Clamp Current	$-5 < V_{IN} \leq -1$	$-25 + (V_{IN} + 1)/0.015$		mA
$slew_R$	Output Rise Slew Rate ⁴	0.4V to 2.4V load	1	5	V/ns
$slew_F$	Output Fall Slew Rate ⁴	2.4V to 0.4V load	1	5	V/ns

Notes:

1. Refer to the V/I curves in Figure 9 on page 14. Switching current characteristics for REQ# and GNT# are permitted to be one half of that specified here; i.e., half size output drivers may be used on these signals. This specification does not apply to CLK and RST# which are system outputs. "Switching Current High" specification are not relevant to SERR#, INTA#, INTB#, INTC#, and INTD# which are open drain outputs.
2. Note that this segment of the minimum current curve is drawn from the AC drive point directly to the DC drive point rather than toward the voltage rail (as is done in the pull-down curve). This difference is intended to allow for an optional N-channel pull-up.
3. Maximum current requirements must be met as drivers pull beyond the last step voltage. Equations defining these maximums (A and B) are provided with the respective diagrams in Figure 9 on page 14. The equation defined maxima should be met by design. In order to facilitate component testing, a maximum current test point is defined for each side of the output driver.
4. This parameter is to be interpreted as the cumulative edge rate across the specified range, rather than the instantaneous rate at any point within the transition range. The specified load (diagram below) is optional; i.e., the designer may elect to meet this parameter with an unloaded output per revision 2.0 of the PCI Local Bus Specification. However, adherence to both maximum and minimum parameters is now required (the maximum is no longer simply a guideline). Since adherence to the maximum slew rate was not required prior to revision 2.1 of the specification, there may be components in the market for some time that have faster edge rates; therefore, motherboard designers must bear in mind that rise and fall times faster than this specification could occur, and should ensure that signal integrity modeling accounts for this. Rise slew rate does not apply to open drain outputs.

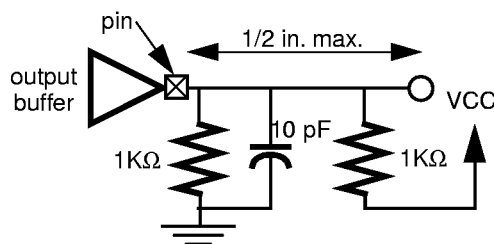


Figure 9 shows the 5.0VPCI VI curve and the minimum and maximum PCI drive characteristics of the SX-A family.

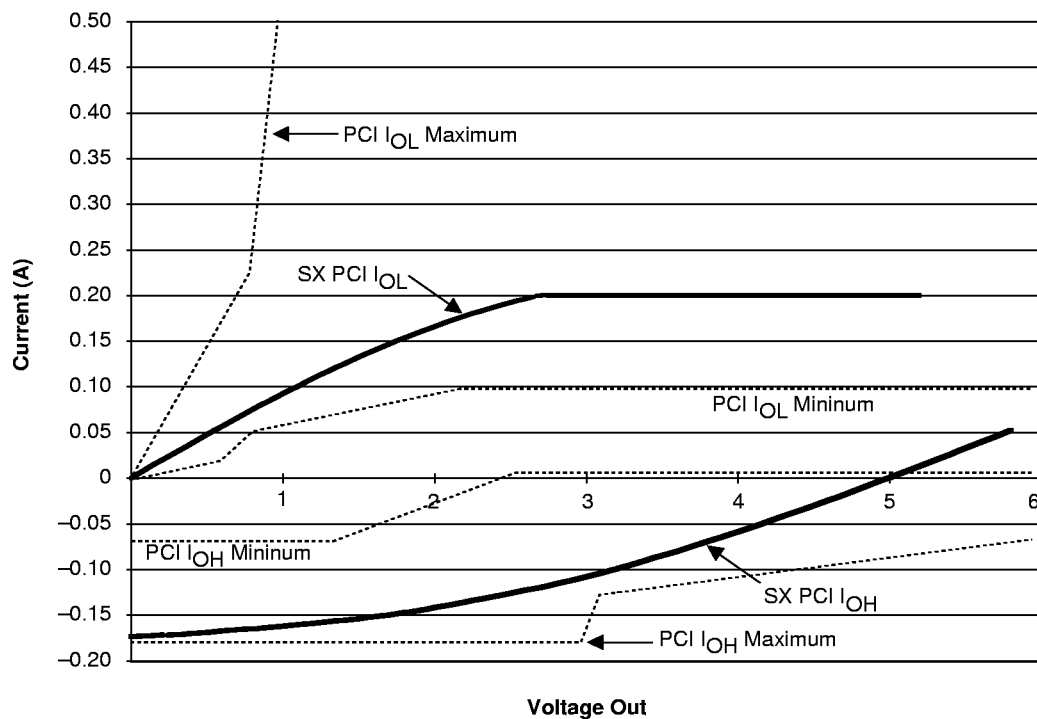


Figure 9 • 5.0VPCI Curve for SX-A Family

Equation A:

$$I_{OH} = 11.9 * (V_{OUT} - 5.25) * (V_{OUT} + 2.45)$$

for $V_{CC1} > V_{OUT} > 3.1V$

Equation B:

$$I_{OL} = 78.5 * V_{OUT} * (4.4 - V_{OUT})$$

for $0V < V_{OUT} < 0.71V$

DC Specifications (3.3V PCI Operation)

Symbol	Parameter	Condition	Min.	Max.	Units
V_{CCA}	Supply Voltage for Array		2.3	2.7	V
V_{CCI}	Supply Voltage for IOs		3.0	3.6	V
V_{IH}	Input High Voltage		$0.5V_{CCI}$	$V_{CCI} + 0.5$	V
V_{IL}	Input Low Voltage		-0.5	$0.3V_{CCI}$	V
I_{IPU}	Input Pull-up Voltage ¹		$0.7V_{CCI}$		V
I_{IL}	Input Leakage Current ²	$0 < V_{IN} < V_{CCI}$		± 10	μA
V_{OH}	Output High Voltage	$I_{OUT} = -500 \mu A$	$0.9V_{CCI}$		V
V_{OL}	Output Low Voltage	$I_{OUT} = 1500 \mu A$		$0.1V_{CCI}$	V
C_{IN}	Input Pin Capacitance ³			10	pF
C_{CLK}	CLK Pin Capacitance		5	12	pF

Notes:

1. This specification should be guaranteed by design. It is the minimum voltage to which pull-up resistors are calculated to pull a floated network. Applications sensitive to static power utilization should assure that the input buffer is conducting minimum current at this input voltage.
2. Input leakage currents include hi-Z output leakage for all bi-directional buffers with tri-state outputs.
3. Absolute maximum pin capacitance for a PCI input is 10pF (except for CLK) with an exception granted to motherboard-only devices, which could be up to 16 pF, in order to accommodate PGA packaging. This would mean in general that components for expansion boards would need to use alternatives to ceramic PGA packaging. This would mean in general that components for expansion boards would need to use alternatives to ceramic packaging; i.e., PQFP, SGA, etc.

AC Specifications (3.3V PCI Operation)

Symbol	Parameter	Condition	Min.	Max.	Units
$I_{OH(AC)}$	Switching ¹ Current High ¹ 1, 2	$0 < V_{OUT} \leq 0.3V_{CCI}$ $0.3V_{CCI} \leq V_{OUT} < 0.9V_{CCI}$ $0.7V_{CCI} < V_{OUT} < V_{CCI}$	$-12V_{CCI}$ $(-17.1 + (V_{CCI} - V_{OUT}))$	Eq. C	mA mA
	(Test Point) ²	$V_{OUT} = 0.7V_{CC}$			
$I_{OL(AC)}$	Switching ¹ Current Low ¹ 1, 2	$V_{CCI} > V_{OUT} \geq 0.6V_{CCI}$ $0.6V_{CCI} > V_{OUT} > 0.1V_{CCI}$ $0.18V_{CCI} > V_{OUT} > 0$	$16V_{CCI}$ $(26.7V_{OUT})$	Eq. D	mA mA
	(Test Point) ²	$V_{OUT} = 0.18V_{CC}$			
I_{CL}	Low Clamp Current	$-3 < V_{IN} \leq -1$	$-25 + (V_{IN} + 1)/0.015$		mA
I_{CH}	High Clamp Current	$V_{CCI} + 4 > V_{IN} \geq V_{CCI} + 1$	$25 + (V_{IN} - V_{CCI} - 1)/0.015$		mA
$slew_R$	Output Rise Slew Rate ³	$0.2V_{CCI}$ to $0.6V_{CCI}$ load	1	4	V/ns
$slew_F$	Output Fall Slew Rate ³	$0.6V_{CCI}$ to $0.2V_{CCI}$ load	1	4	V/ns

Notes:

1. Refer to the V/I curves in Figure 10 on page 17. Switching current characteristics for REQ# and GNT# are permitted to be one half of that specified here; i.e., half size output drivers may be used on these signals. This specification does not apply to CLK and RST# which are system outputs. "Switching Current High" specification are not relevant to SERR#, INTA#, INTB#, INTC#, and INTD# which are open drain outputs.
2. Maximum current requirements must be met as drivers pull beyond the last step voltage. Equations defining these maximums (C and D) are provided with the respective diagrams in Figure 10 on page 17. The equation defined maxima should be met by design. In order to facilitate component testing, a maximum current test point is defined for each side of the output driver.
3. This parameter is to be interpreted as the cumulative edge rate across the specified range, rather than the instantaneous rate at any point within the transition range. The specified load (diagram below) is optional; i.e., the designer may elect to meet this parameter with an unloaded output per the latest revision of the PCI Local Bus Specification. However, adherence to both maximum and minimum parameters is required (the maximum is no longer simply a guideline). Rise slew rate does not apply to open drain outputs.

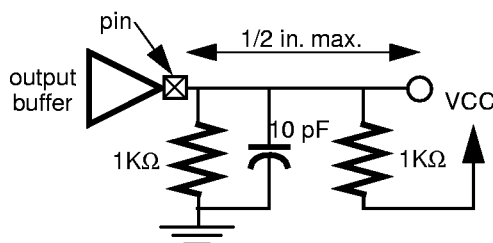


Figure 10 shows the 3.3VPCI VI curve and the minimum and maximum PCI drive characteristics of the SX-A family.

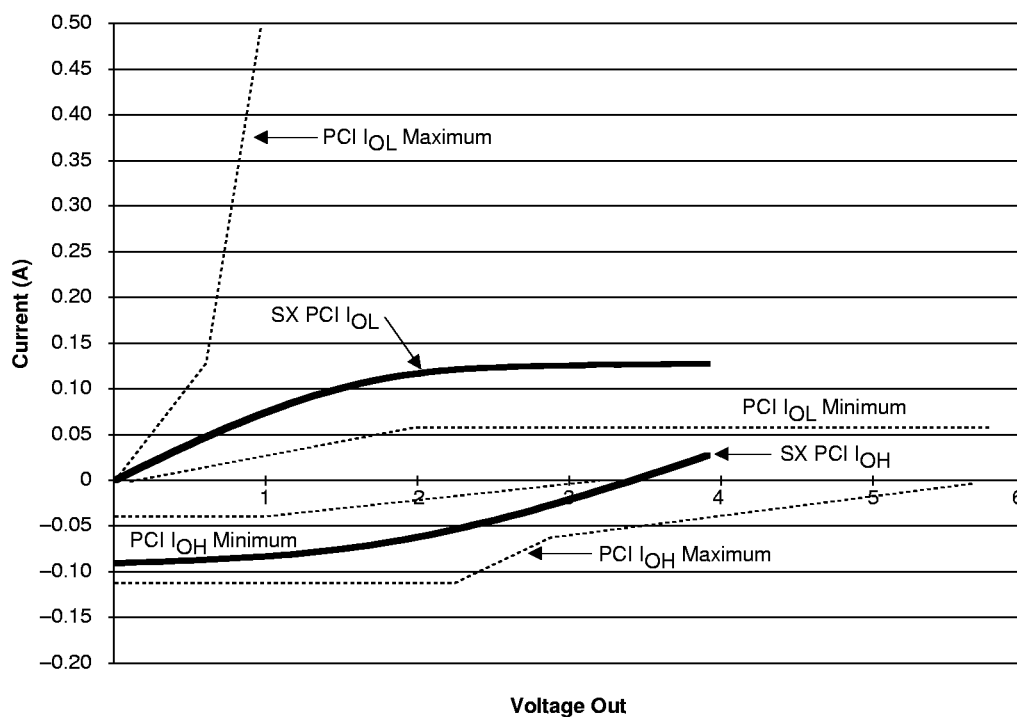


Figure 10 • 3.3VPCI Curve for SX-A Family

Equation C:

$$I_{OH} = (98.0/V_{CC}) * (V_{OUT} - V_{CC}) * (V_{OUT} + 0.4V_{CC})$$

for $V_{CC} > V_{OUT} > 0.7 V_{CC}$

Equation D:

$$I_{OL} = (256/V_{CC}) * V_{OUT} * (V_{CC} - V_{OUT})$$

for $0V < V_{OUT} < 0.18 V_{CC}$

Junction Temperature (T_J)

The temperature that is selected in Designer Series software is the junction temperature, not ambient temperature. This is an important distinction because the heat generated from dynamic power consumption is usually hotter than the ambient temperature. Equation 4, shown below, can be used to calculate junction temperature.

$$\text{Junction Temperature} = \Delta T + T_a \quad (4)$$

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$$\Delta T = \theta_{ja} * P$$

P = Power calculated from Estimating Power Consumption section

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located in the Package Thermal Characteristics section.

Package Thermal Characteristics

The device junction to case thermal characteristic is θ_{jc} , and the junction to ambient air characteristic is θ_{ja} . The thermal characteristics for θ_{ja} are shown with two different air flow rates.

The maximum junction temperature is 150°C.

A sample calculation of the absolute maximum power dissipation allowed for a TQFP 144-pin package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. (°C)} - \text{Max. ambient temp. (°C)}}{\theta_{ja}(\text{°C/W})} = \frac{150^\circ\text{C} - 70^\circ\text{C}}{28^\circ\text{C/W}} = 2.86\text{W}$$

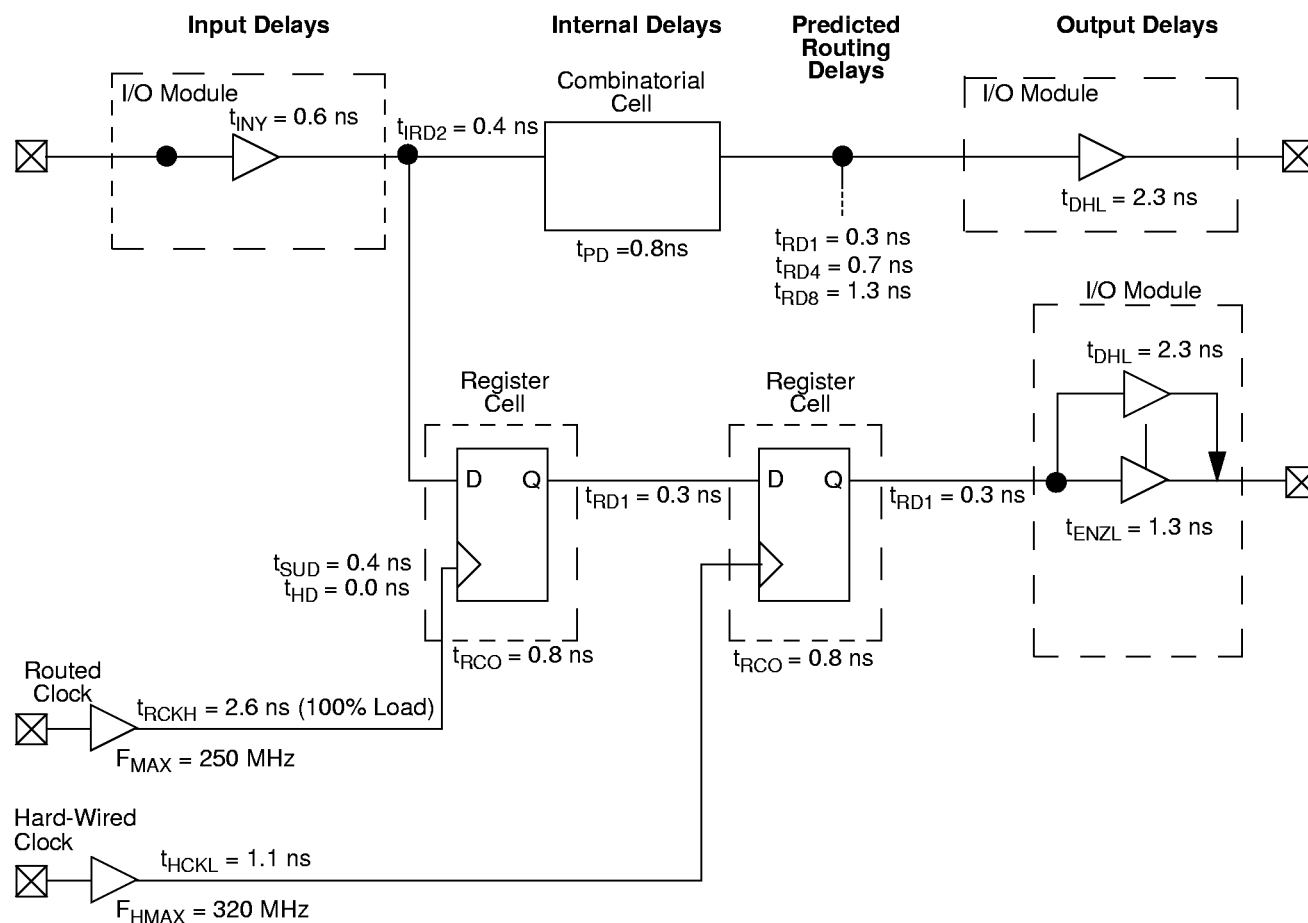
Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 300 ft/min	Units
Thin Quad Flatpack (TQFP)	100	11	38	32	°C/W
Thin Quad Flatpack (TQFP)	144	10	32	24	°C/W
Plastic Quad Flatpack (PQFP) with Heat Spreader	208	8	18	14	°C/W
Plastic Ball Grid Array (PBGA)	329	3	18	13.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	144	3.8	38.8	26.7	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.3	30	25	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	0.8	20	15	°C/W

Temperature and Voltage Derating Factors

(Normalized to Worst-Case Commercial, $T_J = 70^\circ\text{C}$, $V_{CCA} = 2.3\text{V}$)

V_{CCA}	Junction Temperature (T_J)						
	-55	-40	0	25	70	85	125
2.3	0.75	.079	0.88	0.89	1.00	1.04	1.16
2.5	0.70	0.74	0.82	0.83	0.93	0.97	1.08
2.7	0.66	0.69	0.79	0.79	0.88	0.92	1.02

SX-A Timing Model*



*Values shown for A54SX32A-3, worst-case commercial conditions.

Hard-Wired Clock

$$\begin{aligned} \text{External Set-Up} &= t_{INY} + t_{IRD1} + t_{SUD} - t_{HCKL} \\ &= 0.6 + 0.3 + 0.4 - 1.1 = 0.2 \text{ ns} \end{aligned}$$

Clock-to-Out (Pin-to-Pin)

$$\begin{aligned} &= t_{HCKL} + t_{RCO} + t_{RD1} + t_{DHL} \\ &= 1.1 + 0.8 + 0.3 + 2.3 = 4.5 \text{ ns} \end{aligned}$$

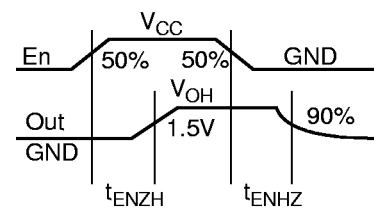
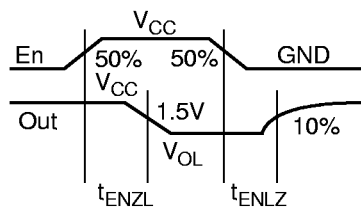
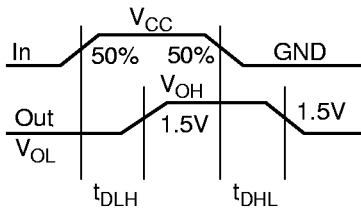
Routed Clock

$$\begin{aligned} \text{External Set-Up} &= t_{INY} + t_{IRD1} + t_{SUD} - t_{RCKH} \\ &= 0.6 + 0.3 + 0.4 - 2.6 = -1.3 \text{ ns} \end{aligned}$$

Clock-to-Out (Pin-to-Pin)

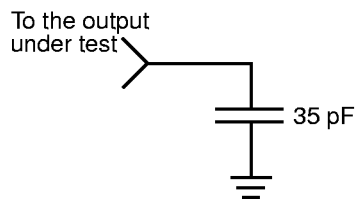
$$\begin{aligned} &= t_{RCKH} + t_{RCO} + t_{RD1} + t_{DHL} \\ &= 2.6 + 0.8 + 0.3 + 2.3 = 6 \text{ ns} \end{aligned}$$

Output Buffer Delays

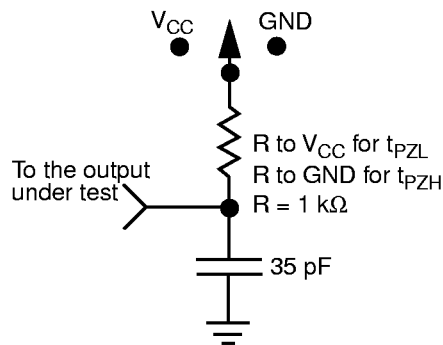


AC Test Loads

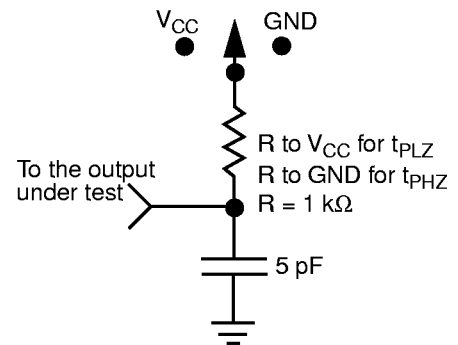
Load 1
(Used to measure propagation delay)



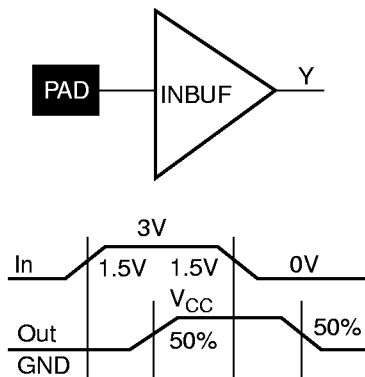
Load 2
(Used to measure enable delays)



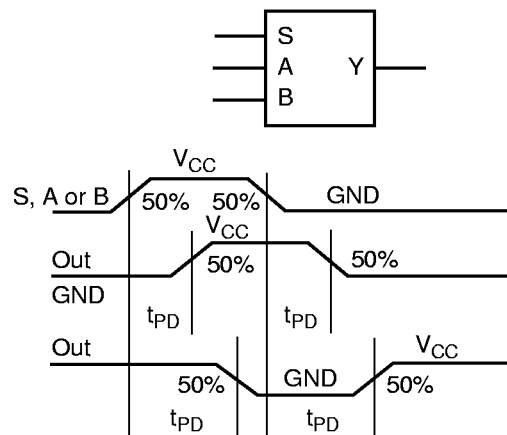
Load 3
(Used to measure disable delays)



Input Buffer Delays

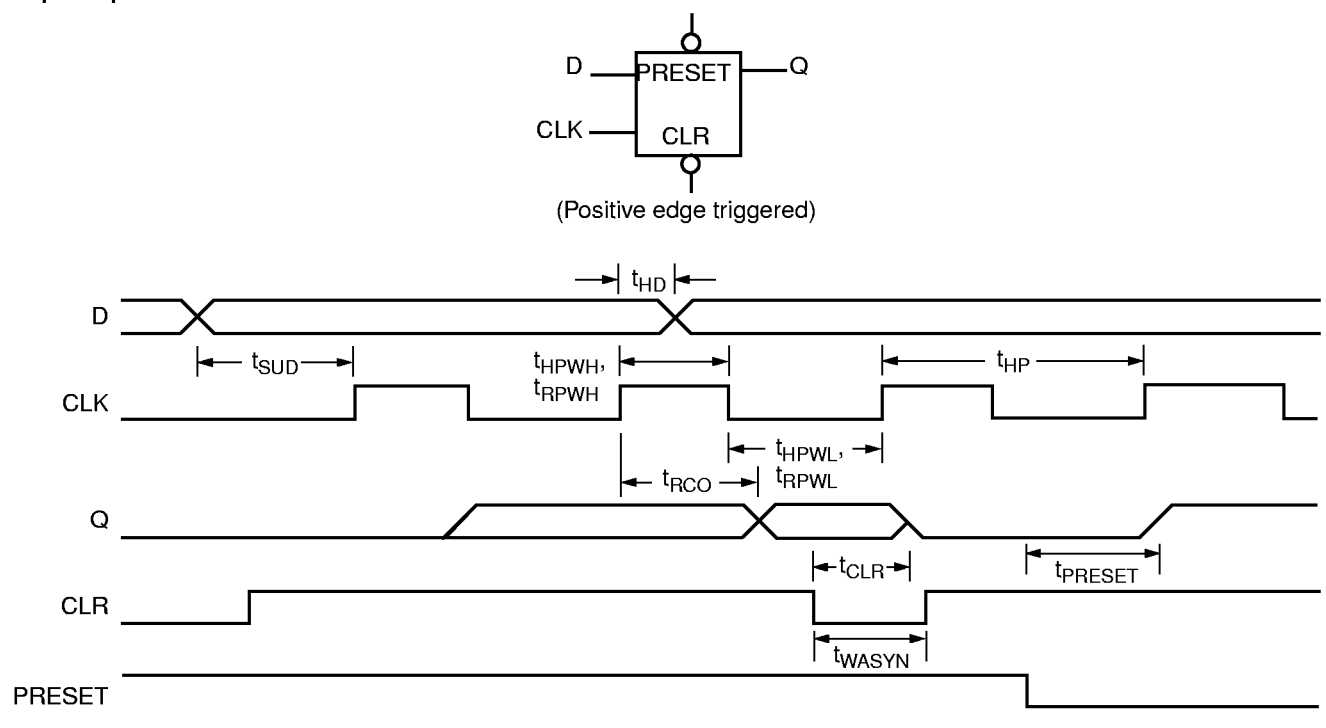


C-Cell Delays



Cell Timing Characteristics

Flip-Flops



Timing Characteristics

Timing characteristics for SX-A devices fall into three categories: family-dependent, device-dependent, and design-dependent. The input and output buffer characteristics are common to all SX-A family members. Internal routing delays are device dependent. Design dependency means actual delays are not determined until after placement and routing of the user's design is complete. Delay values may then be determined by using the DirectTime Analyzer utility or performing simulation with post-layout delays.

Critical Nets and Typical Nets

Propagation delays are expressed only for typical nets, which are used for initial design performance evaluation. Critical net delays can then be applied to the most time-critical paths. Critical nets are determined by net property assignment prior to placement and routing. Up to 6% of the nets in a design may be designated as critical, while 90% of the nets in a design are typical.

Long Tracks

Some nets in the design use long tracks. Long tracks are special routing resources that span multiple rows, columns, or modules. Long tracks employ three and sometimes five antifuse connections. This increases capacitance and resistance, resulting in longer net delays for macros connected to long tracks. Typically up to 6% of nets in a fully utilized device require long tracks. Long tracks contribute approximately 4 ns to 8.4 ns delay. This additional delay is represented statistically in higher fanout (FO=24) routing delays in the data sheet specifications section.

Timing Derating

SX-A devices are manufactured in a CMOS process. Therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing.

A54SX32A Timing Characteristics

(Worst-Case Commercial Conditions, $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^{\circ}C$)

C-Cell Propagation Delays ¹		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{PD}	Internal Array Module		0.8		0.9		1.1		1.3	ns
Predicted Routing Delays ²										
t_{DC}	FO=1 Routing Delay, Direct Connect		0.1		0.1		0.1		0.1	ns
t_{FC}	FO=1 Routing Delay, Fast Connect		0.2		0.2		0.2		0.2	ns
t_{RD1}	FO=1 Routing Delay		0.3		0.3		0.4		0.5	ns
t_{RD2}	FO=2 Routing Delay		0.4		0.5		0.6		0.7	ns
t_{RD3}	FO=3 Routing Delay		0.6		0.7		0.8		0.9	ns
t_{RD4}	FO=4 Routing Delay		0.7		0.9		1.0		1.1	ns
t_{RD8}	FO=8 Routing Delay		1.3		1.5		1.7		2.1	ns
t_{RD12}	FO=12 Routing Delay		1.9		2.2		2.5		3.0	ns
R-Cell Timing										
t_{RCO}	Sequential Clock-to-Q		0.8		0.9		1.0		1.2	ns
t_{CLR}	Asynchronous Clear-to-Q		0.6		0.7		0.8		0.9	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.7		0.8		0.9		1.1	ns
t_{SUD}	Flip-Flop Data Input Set-Up	0.4		0.5		0.6		0.7		ns
t_{HD}	Flip-Flop Data Input Hold	0.0		0.0		0.0		0.0		ns
t_{WASYN}	Asynchronous Pulse Width	1.0		1.2		1.4		1.6		ns

Notes:

1. For dual-module macros, use $t_{PD} + t_{RDI} + t_{PDn}$, $t_{RCO} + t_{RDI} + t_{PDn}$ or $t_{PD} + t_{RDI} + t_{SUD}$, whichever is appropriate.
2. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual worst-case performance. Post-route timing is based on actual routing delay measurements performed on the device prior to shipment.

A54SX32A Timing Characteristics (Continued)

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

I/O Module Input Propagation Delays		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{INYH}	Input Data Pad-to-Y HIGH		0.6		0.7		0.8		0.9	ns
t_{INYL}	Input Data Pad-to-Y LOW		0.9		1.0		1.2		1.4	ns
Predicted Input Routing Delays¹										
t_{IRD1}	FO=1 Routing Delay		0.3		0.3		0.4		0.5	ns
t_{IRD2}	FO=2 Routing Delay		0.4		0.5		0.6		0.7	ns
t_{IRD3}	FO=3 Routing Delay		0.6		0.7		0.8		0.9	ns
t_{IRD4}	FO=4 Routing Delay		0.7		0.9		1.0		1.1	ns
t_{IRD8}	FO=8 Routing Delay		1.3		1.5		1.7		2.1	ns
t_{IRD12}	FO=12 Routing Delay		1.9		2.2		2.5		3.0	ns

Note:

1. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual worst-case performance. Post-route timing is based on actual routing delay measurements performed on the device prior to shipment.

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

I/O Module – PCI Output Timing ¹		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		2.4		2.8		3.2		3.7	ns
t_{DHL}	Data-to-Pad HIGH to LOW		2.3		2.7		3.1		3.6	ns
t_{ENZL}	Enable-to-Pad, Z to L		1.3		1.5		1.7		2.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		1.6		1.9		2.1		2.5	ns
t_{ENLZ}	Enable-to-Pad, L to Z		2.6		2.9		3.3		3.9	ns
t_{ENHZ}	Enable-to-Pad, H to Z		2.9		3.3		3.8		4.4	ns

Note:

1. Delays based on 10pF loading.

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

I/O Module – TTL Output Timing		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		3.2		3.7		4.2		4.9	ns
t_{DHL}	Data-to-Pad HIGH to LOW		2.8		3.3		3.7		4.4	ns
t_{ENZL}	Enable-to-Pad, Z to L		2.6		3.0		3.4		4.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		3.2		3.7		4.2		4.9	ns
t_{ENLZ}	Enable-to-Pad, L to Z		2.1		3.2		3.6		4.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z		3.3		3.8		4.3		5.0	ns

A54SX32A Timing Characteristics (Continued)

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 4.75V$, $T_J = 70^\circ C$)

I/O Module – TTL Output Timing		‘–3’ Speed		‘–2’ Speed		‘–1’ Speed		‘Std’ Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		2.5		2.9		3.3		3.9	ns
t_{DHL}	Data-to-Pad HIGH to LOW		3.1		3.6		4.1		4.8	ns
t_{ENZL}	Enable-to-Pad, Z to L		2.6		3.0		3.4		4.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		2.3		2.7		3.0		3.6	ns
t_{ENLZ}	Enable-to-Pad, L to Z		3.4		3.9		4.4		5.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z		4.2		4.8		5.5		6.313	ns

(Worst-Case Commercial Conditions $V_{CCA} = 3.0V$, $V_{CCI} = 4.75V$, $T_J = 70^\circ C$)

I/O Module – PCI Output Timing		‘–3’ Speed		‘–2’ Speed		‘–1’ Speed		‘Std’ Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		2.8		3.2		3.7		4.3	ns
t_{DHL}	Data-to-Pad HIGH to LOW		3.4		3.9		4.5		5.3	ns
t_{ENZL}	Enable-to-Pad, Z to L		1.3		1.5		1.7		2.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		1.5		1.7		1.9		2.2	ns
t_{ENLZ}	Enable-to-Pad, L to Z		2.6		3.0		3.5		4.1	ns
t_{ENHZ}	Enable-to-Pad, H to Z		3.3		3.9		4.4		5.2	ns

A54SX32A Timing Characteristics (Continued)(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

Dedicated (Hard-Wired) Array Clock Network		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{HCKH}	Input LOW to HIGH (Pad to R-Cell Input)		1.3		1.4		1.6		1.9	ns
t_{HCKL}	Input HIGH to LOW (Pad to R-Cell Input)		1.1		1.3		1.4		1.7	ns
t_{HPWH}	Minimum Pulse Width HIGH	1.4		1.6		1.8		2.1		ns
t_{HPWL}	Minimum Pulse Width LOW	1.4		1.6		1.8		2.1		ns
t_{HCKSW}	Maximum Skew		0.1		0.2		0.2		0.2	ns
t_{HP}	Minimum Period	2.7		3.1		3.6		4.2		ns
f_{HMAX}	Maximum Frequency		350		320		280		240	MHz
Routed Array Clock Networks										
t_{RCKH}	Input LOW to HIGH (Light Load) (Pad to R-Cell Input)		1.8		2.1		2.4		2.8	ns
t_{RCKL}	Input HIGH to LOW (Light Load) (Pad to R-Cell Input)		2.0		2.3		2.6		3.0	ns
t_{RCKH}	Input LOW to HIGH (50% Load) (Pad to R-Cell Input)		2.0		2.4		2.7		3.1	ns
t_{RCKL}	Input HIGH to LOW (50% Load) (Pad to R-Cell Input)		2.2		2.5		2.8		3.3	ns
t_{RCKH}	Input LOW to HIGH (100% Load) (Pad to R-Cell Input)		2.6		3.0		3.4		4.0	ns
t_{RCKL}	Input HIGH to LOW (100% Load) (Pad to R-Cell Input)		2.6		3.0		3.4		4.0	ns
t_{RPWH}	Min. Pulse Width HIGH	2.1		2.4		2.7		3.2		ns
t_{RPWL}	Min. Pulse Width LOW	2.1		2.4		2.7		3.2		ns
t_{RCKSW}	Maximum Skew (Light Load)		0.9		1.0		1.1		1.3	ns
t_{RCKSW}	Maximum Skew (50% Load)		1.2		1.4		1.6		1.9	ns
t_{RCKSW}	Maximum Skew (100% Load)		1.3		1.5		1.7		2.0	ns

A54SX72A Timing Characteristics

(Worst-Case Commercial Conditions, $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

C-Cell Propagation Delays ¹		‘-3’ Speed		‘-2’ Speed		‘-1’ Speed		‘Std’ Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{PD}	Internal Array Module		0.8		0.9		1.1		1.3	ns
Predicted Routing Delays ²										
t_{DC}	FO=1 Routing Delay, Direct Connect		0.1		0.1		0.1		0.1	ns
t_{FC}	FO=1 Routing Delay, Fast Connect		0.1		0.2		0.2		0.2	ns
t_{RD1}	FO=1 Routing Delay		0.3		0.3		0.4		0.5	ns
t_{RD2}	FO=2 Routing Delay		0.4		0.5		0.6		0.7	ns
t_{RD3}	FO=3 Routing Delay		0.6		0.7		0.8		0.9	ns
t_{RD4}	FO=4 Routing Delay		0.7		0.9		1.0		1.1	ns
t_{RD8}	FO=8 Routing Delay		1.3		1.5		1.7		2.1	ns
t_{RD12}	FO=12 Routing Delay		1.9		2.2		2.5		3.0	ns
R-Cell Timing										
t_{RCO}	Sequential Clock-to-Q		0.8		0.9		1.0		1.2	ns
t_{CLR}	Asynchronous Clear-to-Q		0.6		0.7		0.8		0.9	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.7		0.8		0.9		1.1	ns
t_{SUD}	Flip-Flop Data Input Set-Up	0.4		0.5		0.6		0.7		ns
t_{HD}	Flip-Flop Data Input Hold	0.0		0.0		0.0		0.0		ns
t_{WASYN}	Asynchronous Pulse Width	1.0		1.2		1.4		1.6		ns

Notes:

1. For dual-module macros, use $t_{PD} + t_{RDI} + t_{PDn}$, $t_{RCO} + t_{RDI} + t_{PDn}$ or $t_{PD} + t_{RDI} + t_{SUD}$, whichever is appropriate.
2. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual worst-case performance. Post-route timing is based on actual routing delay measurements performed on the device prior to shipment.

A54SX72A Timing Characteristics (Continued)

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

I/O Module Input Propagation Delays		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{INYH}	Input Data Pad-to-Y HIGH		0.6		0.7		0.8		0.9	ns
t_{INYL}	Input Data Pad-to-Y LOW		0.9		1.0		1.2		1.4	ns
Predicted Input Routing Delays¹										
t_{IRD1}	FO=1 Routing Delay		0.3		0.3		0.4		0.5	ns
t_{IRD2}	FO=2 Routing Delay		0.4		0.5		0.6		0.7	ns
t_{IRD3}	FO=3 Routing Delay		0.6		0.7		0.8		0.9	ns
t_{IRD4}	FO=4 Routing Delay		0.7		0.9		1.0		1.1	ns
t_{IRD8}	FO=8 Routing Delay		1.3		1.5		1.7		2.1	ns
t_{IRD12}	FO=12 Routing Delay		1.9		2.2		2.5		3.0	ns

Note:

1. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual worst-case performance. Post-route timing is based on actual routing delay measurements performed on the device prior to shipment.

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

I/O Module – PCI Output Timing ¹		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		2.4		2.8		3.2		3.7	ns
t_{DHL}	Data-to-Pad HIGH to LOW		2.3		2.7		3.1		3.6	ns
t_{ENZL}	Enable-to-Pad, Z to L		1.3		1.5		1.7		2.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		1.6		1.9		2.1		2.5	ns
t_{ENLZ}	Enable-to-Pad, L to Z		2.6		2.9		3.3		3.9	ns
t_{ENHZ}	Enable-to-Pad, H to Z		2.9		3.3		3.8		4.4	ns

Note:

1. Delays based on 10pF loading.

Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

I/O Module – TTL Output Timing		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		3.2		3.7		4.2		4.9	ns
t_{DHL}	Data-to-Pad HIGH to LOW		2.8		3.3		3.7		4.4	ns
t_{ENZL}	Enable-to-Pad, Z to L		2.6		3.0		3.4		4.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		3.2		3.7		4.2		4.9	ns
t_{ENLZ}	Enable-to-Pad, L to Z		2.1		3.2		3.6		4.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z		3.3		3.8		4.3		5.0	ns

A54SX72A Timing Characteristics (Continued)

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 4.75V$, $T_J = 70^\circ C$)

I/O Module – TTL Output Timing		‘–3’ Speed		‘–2’ Speed		‘–1’ Speed		‘Std’ Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		2.5		2.9		3.3		3.9	ns
t_{DHL}	Data-to-Pad HIGH to LOW		3.1		3.6		4.1		4.8	ns
t_{ENZL}	Enable-to-Pad, Z to L		2.6		3.0		3.4		4.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		2.3		2.7		3.0		3.6	ns
t_{ENLZ}	Enable-to-Pad, L to Z		3.4		3.9		4.4		5.2	ns
t_{ENHZ}	Enable-to-Pad, H to Z		4.2		4.8		5.5		6.3	ns

(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 4.75V$, $T_J = 70^\circ C$)

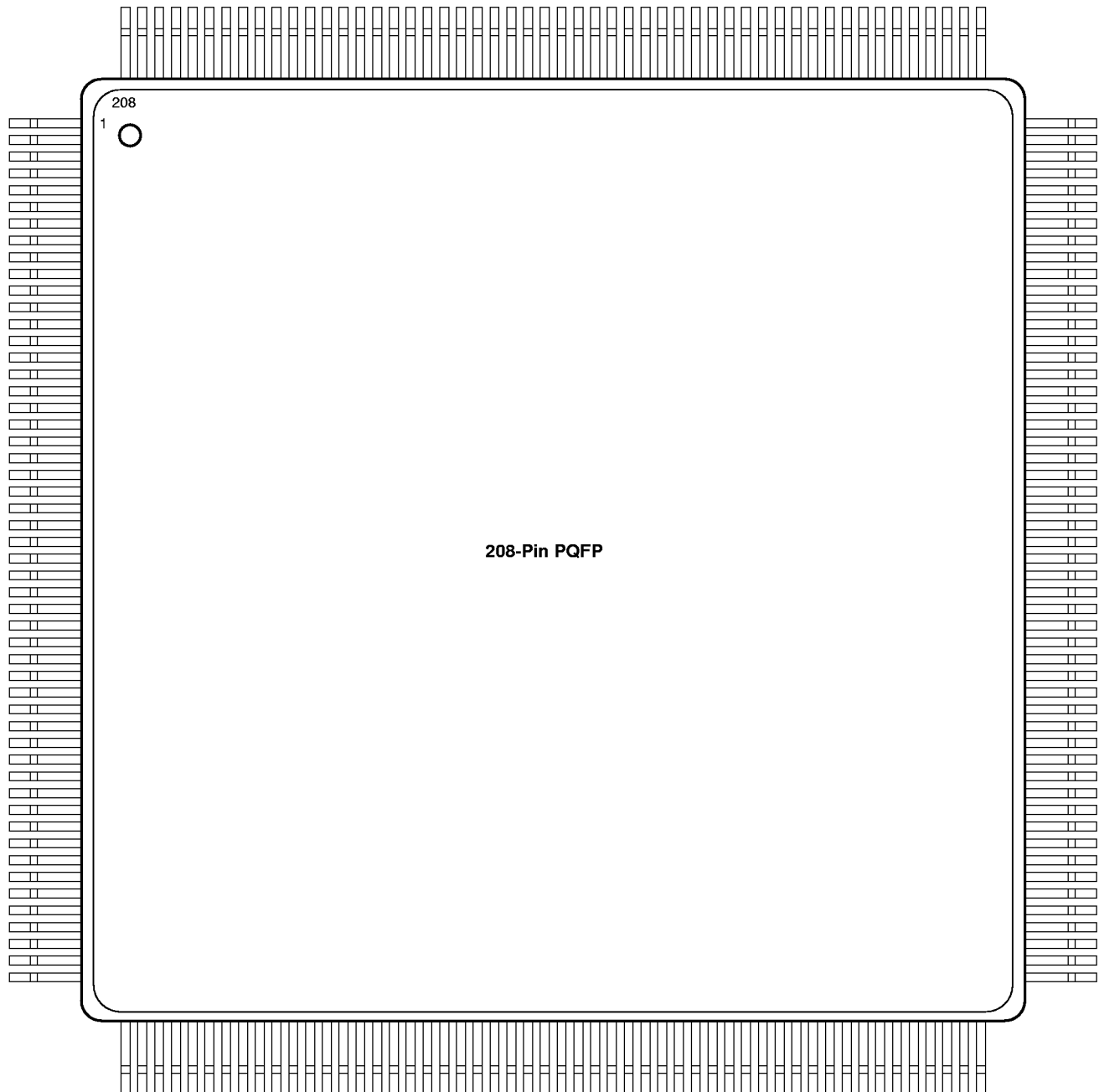
I/O Module – PCI Output Timing		‘–3’ Speed		‘–2’ Speed		‘–1’ Speed		‘Std’ Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{DLH}	Data-to-Pad LOW to HIGH		2.8		3.2		3.7		4.3	ns
t_{DHL}	Data-to-Pad HIGH to LOW		3.4		3.9		4.5		5.3	ns
t_{ENZL}	Enable-to-Pad, Z to L		1.3		1.5		1.7		2.0	ns
t_{ENZH}	Enable-to-Pad, Z to H		1.5		1.7		1.9		2.2	ns
t_{ENLZ}	Enable-to-Pad, L to Z		2.6		3.0		3.5		4.1	ns
t_{ENHZ}	Enable-to-Pad, H to Z		3.3		3.9		4.4		5.2	ns

A54SX72A Timing Characteristics (Continued)(Worst-Case Commercial Conditions $V_{CCA} = 2.3V$, $V_{CCI} = 3.0V$, $T_J = 70^\circ C$)

Dedicated (Hard-Wired) Array Clock Network		'-3' Speed		'-2' Speed		'-1' Speed		'Std' Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
t_{HCKH}	Input LOW to HIGH (Pad to R-Cell Input)		1.6		1.9		2.1		2.5	ns
t_{HCKL}	Input HIGH to LOW (Pad to R-Cell Input)		1.4		1.6		1.8		2.2	ns
t_{HPWH}	Minimum Pulse Width HIGH	1.4		1.6		1.8		2.1		ns
t_{HPWL}	Minimum Pulse Width LOW	1.4		1.6		1.8		2.1		ns
t_{HCKSW}	Maximum Skew		0.3		0.4		0.4		0.5	ns
t_{HP}	Minimum Period	2.7		3.1		3.6		4.2		ns
f_{HMAX}	Maximum Frequency		350		320		280		240	MHz
Routed Array Clock Networks										
t_{RCKH}	Input LOW to HIGH (Light Load) (Pad to R-Cell Input)		2.8		3.2		3.6		4.2	ns
t_{RCKL}	Input HIGH to LOW (Light Load) (Pad to R-Cell Input)		2.9		3.4		3.8		4.5	ns
t_{RCKH}	Input LOW to HIGH (50% Load) (Pad to R-Cell Input)		3.4		3.9		4.4		5.2	ns
t_{RCKL}	Input HIGH to LOW (50% Load) (Pad to R-Cell Input)		3.5		4.0		4.5		5.3	ns
t_{RCKH}	Input LOW to HIGH (100% Load) (Pad to R-Cell Input)		4.6		5.3		6.0		7.0	ns
t_{RCKL}	Input HIGH to LOW (100% Load) (Pad to R-Cell Input)		4.6		5.3		6.0		7.1	ns
t_{RPWH}	Min. Pulse Width HIGH	2.1		2.4		2.7		3.2		ns
t_{RPWL}	Min. Pulse Width LOW	2.1		2.4		2.7		3.2		ns
t_{RCKSW}	Maximum Skew (Light Load)		0.9		1.0		1.1		1.3	ns
t_{RCKSW}	Maximum Skew (50% Load)		1.2		1.4		1.6		1.9	ns
t_{RCKSW}	Maximum Skew (100% Load)		1.3		1.5		1.7		2.0	ns

Package Pin Assignments

208-Pin PQFP (Top View)



208-Pin PQFP

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
1	GND	GND	GND	GND
2	TDI, I/O	TDI, I/O	TDI, I/O	TDI, I/O
3	I/O	I/O	I/O	I/O
4	NC	I/O	I/O	I/O
5	I/O	I/O	I/O	I/O
6	NC	I/O	I/O	I/O
7	I/O	I/O	I/O	I/O
8	I/O	I/O	I/O	I/O
9	I/O	I/O	I/O	I/O
10	I/O	I/O	I/O	I/O
11	TMS	TMS	TMS	TMS
12	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
13	I/O	I/O	I/O	I/O
14	NC	I/O	I/O	I/O
15	I/O	I/O	I/O	I/O
16	I/O	I/O	I/O	I/O
17	NC	I/O	I/O	I/O
18	I/O	I/O	I/O	GND
19	I/O	I/O	I/O	V _{CCA}
20	NC	I/O	I/O	I/O
21	I/O	I/O	I/O	I/O
22	I/O	I/O	I/O	I/O
23	NC	I/O	I/O	I/O
24	I/O	I/O	I/O	I/O
25	NC	NC	NC	I/O
26	GND	GND	GND	GND
27	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
28	GND	GND	GND	GND
29	I/O	I/O	I/O	I/O
30	TRST, I/O	TRST, I/O	TRST, I/O	TRST, I/O
31	NC	I/O	I/O	I/O
32	I/O	I/O	I/O	I/O
33	I/O	I/O	I/O	I/O
34	I/O	I/O	I/O	I/O
35	NC	I/O	I/O	I/O
36	I/O	I/O	I/O	I/O
37	I/O	I/O	I/O	I/O
38	I/O	I/O	I/O	I/O
39	NC	I/O	I/O	I/O
40	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
41	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
42	I/O	I/O	I/O	I/O
43	I/O	I/O	I/O	I/O
44	I/O	I/O	I/O	I/O
45	I/O	I/O	I/O	I/O
46	I/O	I/O	I/O	I/O

*Please note that Pin 65 in the A54SX32A—PQ208 is a no connect (NC).

208-Pin PQFP (Continued)

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
47	I/O	I/O	I/O	I/O
48	NC	I/O	I/O	I/O
49	I/O	I/O	I/O	I/O
50	NC	I/O	I/O	I/O
51	I/O	I/O	I/O	I/O
52	GND	GND	GND	GND
53	I/O	I/O	I/O	I/O
54	I/O	I/O	I/O	I/O
55	I/O	I/O	I/O	I/O
56	I/O	I/O	I/O	I/O
57	I/O	I/O	I/O	I/O
58	I/O	I/O	I/O	I/O
59	I/O	I/O	I/O	I/O
60	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
61	NC	I/O	I/O	I/O
62	I/O	I/O	I/O	I/O
63	I/O	I/O	I/O	I/O
64	NC	I/O	I/O	I/O
65*	I/O	I/O	NC*	I/O
66	I/O	I/O	I/O	I/O
67	NC	I/O	I/O	I/O
68	I/O	I/O	I/O	I/O
69	I/O	I/O	I/O	I/O
70	NC	I/O	I/O	I/O
71	I/O	I/O	I/O	I/O
72	I/O	I/O	I/O	I/O
73	NC	I/O	I/O	I/O
74	I/O	I/O	I/O	QCLKA
75	NC	I/O	I/O	I/O
76	PRB, I/O	PRB, I/O	PRB, I/O	PRB, I/O
77	GND	GND	GND	GND
78	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
79	GND	GND	GND	GND
80	NC	NC	NC	NC
81	I/O	I/O	I/O	I/O
82	HCLK	HCLK	HCLK	HCLK
83	I/O	I/O	I/O	V _{CCI}
84	I/O	I/O	I/O	QCLKB
85	NC	I/O	I/O	I/O
86	I/O	I/O	I/O	I/O
87	I/O	I/O	I/O	I/O
88	NC	I/O	I/O	I/O
89	I/O	I/O	I/O	I/O
90	I/O	I/O	I/O	I/O
91	NC	I/O	I/O	I/O
92	I/O	I/O	I/O	I/O

* Please note that Pin 65 in the A54SX32A—PQ208 is a no connect (NC).

208-Pin PQFP (Continued)

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
93	I/O	I/O	I/O	I/O
94	NC	I/O	I/O	I/O
95	I/O	I/O	I/O	I/O
96	I/O	I/O	I/O	I/O
97	NC	I/O	I/O	I/O
98	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
99	I/O	I/O	I/O	I/O
100	I/O	I/O	I/O	I/O
101	I/O	I/O	I/O	I/O
102	I/O	I/O	I/O	I/O
103	TDO, I/O	TDO, I/O	TDO, I/O	TDO, I/O
104	I/O	I/O	I/O	I/O
105	GND	GND	GND	GND
106	NC	I/O	I/O	I/O
107	I/O	I/O	I/O	I/O
108	NC	I/O	I/O	I/O
109	I/O	I/O	I/O	I/O
110	I/O	I/O	I/O	I/O
111	I/O	I/O	I/O	I/O
112	I/O	I/O	I/O	I/O
113	I/O	I/O	I/O	I/O
114	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
115	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
116	NC	I/O	I/O	GND
117	I/O	I/O	I/O	V _{CCA}
118	I/O	I/O	I/O	I/O
119	NC	I/O	I/O	I/O
120	I/O	I/O	I/O	I/O
121	I/O	I/O	I/O	I/O
122	NC	I/O	I/O	I/O
123	I/O	I/O	I/O	I/O
124	I/O	I/O	I/O	I/O
125	NC	I/O	I/O	I/O
126	I/O	I/O	I/O	I/O
127	I/O	I/O	I/O	I/O
128	I/O	I/O	I/O	I/O
129	GND	GND	GND	GND
130	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
131	GND	GND	GND	GND
132	NC	NC	NC	I/O
133	I/O	I/O	I/O	I/O
134	I/O	I/O	I/O	I/O
135	NC	I/O	I/O	I/O
136	I/O	I/O	I/O	I/O
137	I/O	I/O	I/O	I/O
138	NC	I/O	I/O	I/O

*Please note that Pin 65 in the A54SX32A—PQ208 is a no connect (NC).

208-Pin PQFP (Continued)

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
139	I/O	I/O	I/O	I/O
140	I/O	I/O	I/O	I/O
141	NC	I/O	I/O	I/O
142	I/O	I/O	I/O	I/O
143	NC	I/O	I/O	I/O
144	I/O	I/O	I/O	I/O
145	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}
146	GND	GND	GND	GND
147	I/O	I/O	I/O	I/O
148	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
149	I/O	I/O	I/O	I/O
150	I/O	I/O	I/O	I/O
151	I/O	I/O	I/O	I/O
152	I/O	I/O	I/O	I/O
153	I/O	I/O	I/O	I/O
154	I/O	I/O	I/O	I/O
155	NC	I/O	I/O	I/O
156	NC	I/O	I/O	I/O
157	GND	GND	GND	GND
158	I/O	I/O	I/O	I/O
159	I/O	I/O	I/O	I/O
160	I/O	I/O	I/O	I/O
161	I/O	I/O	I/O	I/O
162	I/O	I/O	I/O	I/O
163	I/O	I/O	I/O	I/O
164	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
165	I/O	I/O	I/O	I/O
166	I/O	I/O	I/O	I/O
167	NC	I/O	I/O	I/O
168	I/O	I/O	I/O	I/O
169	I/O	I/O	I/O	I/O
170	NC	I/O	I/O	I/O
171	I/O	I/O	I/O	I/O
172	I/O	I/O	I/O	I/O
173	NC	I/O	I/O	I/O
174	I/O	I/O	I/O	I/O
175	I/O	I/O	I/O	I/O
176	NC	I/O	I/O	I/O
177	I/O	I/O	I/O	I/O
178	I/O	I/O	I/O	QCLKD
179	I/O	I/O	I/O	I/O
180	CLKA	CLKA	CLKA	CLKA
181	CLKB	CLKB	CLKB	CLKB
182	NC	NC	NC	NC
183	GND	GND	GND	GND
184	V _{CCA}	V _{CCA}	V _{CCA}	V _{CCA}

*Please note that Pin 65 in the A54SX32A — PQ208 is a no connect (NC).

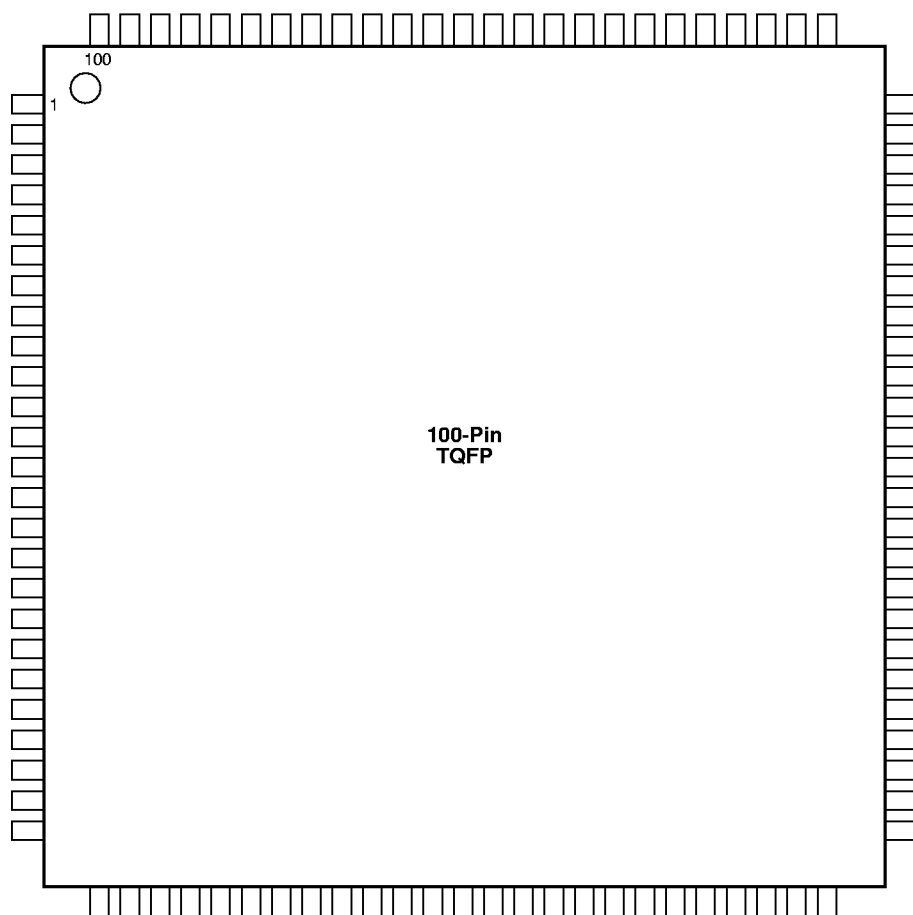
208-Pin PQFP (Continued)

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	A54SX72A Function
185	GND	GND	GND	GND
186	PRA, I/O	PRA, I/O	PRA, I/O	PRA, I/O
187	I/O	I/O	I/O	V _{CCI}
188	I/O	I/O	I/O	I/O
189	NC	I/O	I/O	I/O
190	I/O	I/O	I/O	QCLKC
191	I/O	I/O	I/O	I/O
192	NC	I/O	I/O	I/O
193	I/O	I/O	I/O	I/O
194	I/O	I/O	I/O	I/O
195	NC	I/O	I/O	I/O
196	I/O	I/O	I/O	I/O
197	I/O	I/O	I/O	I/O
198	NC	I/O	I/O	I/O
199	I/O	I/O	I/O	I/O
200	I/O	I/O	I/O	I/O
201	V _{CCI}	V _{CCI}	V _{CCI}	V _{CCI}
202	NC	I/O	I/O	I/O
203	NC	I/O	I/O	I/O
204	I/O	I/O	I/O	I/O
205	NC	I/O	I/O	I/O
206	I/O	I/O	I/O	I/O
207	I/O	I/O	I/O	I/O
208	TCK, I/O	TCK, I/O	TCK, I/O	TCK, I/O

*Please note that Pin 65 in the A54SX32A—PQ208 is a no connect (NC).

Package Pin Assignments (Continued)

100-Pin TQFP (Top View)



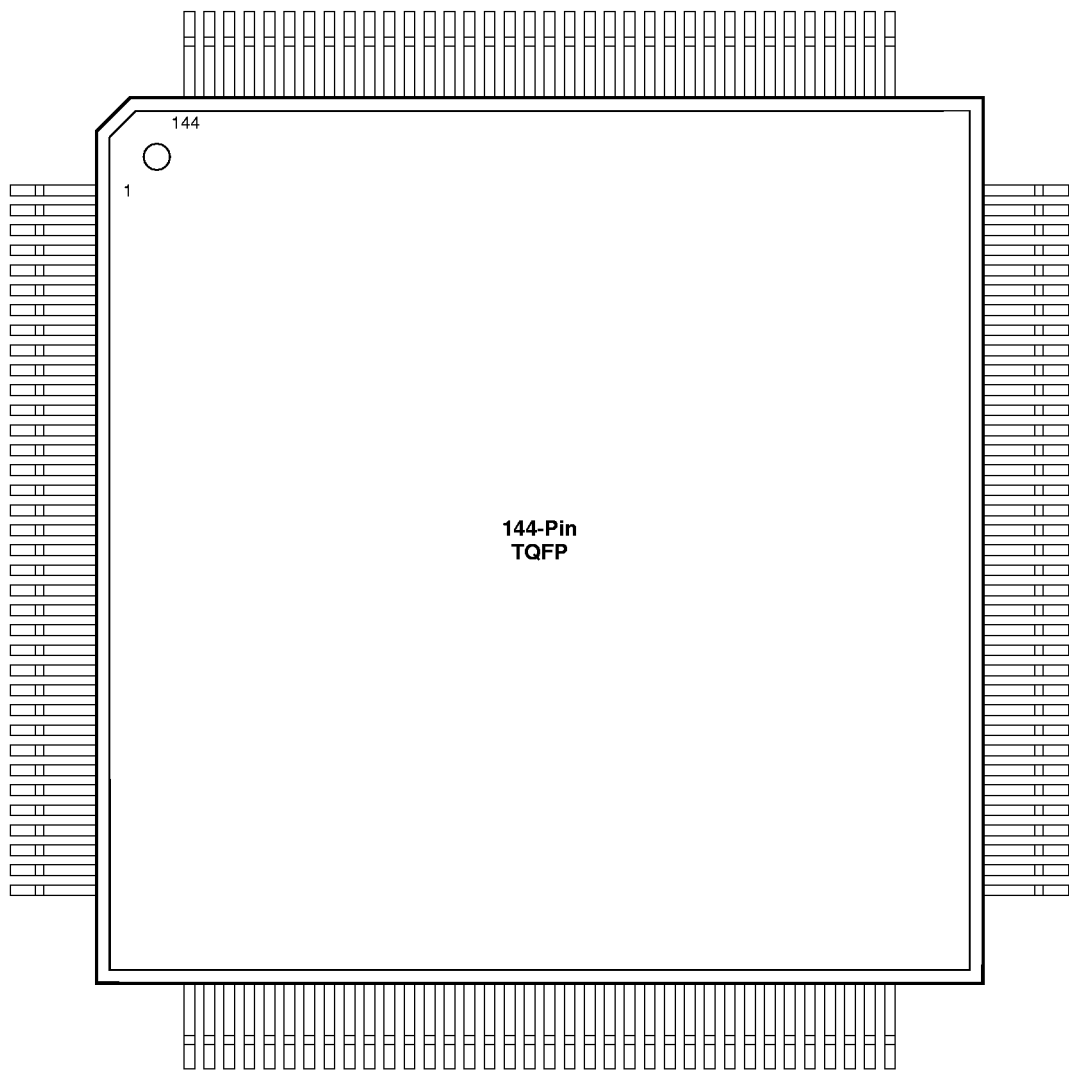
100-TQFP

Pin Number	A54SX08A Function	A54SX16A Function
1	GND	GND
2	TDI, I/O	TDI, I/O
3	I/O	I/O
4	I/O	I/O
5	I/O	I/O
6	I/O	I/O
7	TMS	TMS
8	V _{CCI}	V _{CCI}
9	GND	GND
10	I/O	I/O
11	I/O	I/O
12	I/O	I/O
13	I/O	I/O
14	I/O	I/O
15	I/O	I/O
16	TRST, I/O	TRST, I/O
17	I/O	I/O
18	I/O	I/O
19	I/O	I/O
20	V _{CCI}	V _{CCI}
21	I/O	I/O
22	I/O	I/O
23	I/O	I/O
24	I/O	I/O
25	I/O	I/O
26	I/O	I/O
27	I/O	I/O
28	I/O	I/O
29	I/O	I/O
30	I/O	I/O
31	I/O	I/O
32	I/O	I/O
33	I/O	I/O
34	PRB, I/O	PRB, I/O
35	V _{CCA}	V _{CCA}
36	GND	GND
37	NC	NC
38	I/O	I/O
39	HCLK	HCLK
40	I/O	I/O
41	I/O	I/O
42	I/O	I/O
43	I/O	I/O
44	V _{CCI}	V _{CCI}
45	I/O	I/O
46	I/O	I/O
47	I/O	I/O
48	I/O	I/O
49	TDO, I/O	TDO, I/O
50	I/O	I/O

Pin Number	A54SX08A Function	A54SX16A Function
51	GND	GND
52	I/O	I/O
53	I/O	I/O
54	I/O	I/O
55	I/O	I/O
56	I/O	I/O
57	V _{CCA}	V _{CCA}
58	V _{CCI}	V _{CCI}
59	I/O	I/O
60	I/O	I/O
61	I/O	I/O
62	I/O	I/O
63	I/O	I/O
64	I/O	I/O
65	I/O	I/O
66	I/O	I/O
67	V _{CCA}	V _{CCA}
68	GND	GND
69	GND	GND
70	I/O	I/O
71	I/O	I/O
72	I/O	I/O
73	I/O	I/O
74	I/O	I/O
75	I/O	I/O
76	I/O	I/O
77	I/O	I/O
78	I/O	I/O
79	I/O	I/O
80	I/O	I/O
81	I/O	I/O
82	V _{CCI}	V _{CCI}
83	I/O	I/O
84	I/O	I/O
85	I/O	I/O
86	I/O	I/O
87	CLKA	CLKA
88	CLKB	CLKB
89	NC	NC
90	V _{CCA}	V _{CCA}
91	GND	GND
92	PRA, I/O	PRA, I/O
93	I/O	I/O
94	I/O	I/O
95	I/O	I/O
96	I/O	I/O
97	I/O	I/O
98	I/O	I/O
99	I/O	I/O
100	TCK, I/O	TCK, I/O

Package Pin Assignments (Continued)

144-Pin TQFP (Top View)



144-Pin TQFP

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function	Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
1	GND	GND	GND	39	I/O	I/O	I/O
2	TDI, I/O	TDI, I/O	TDI, I/O	40	I/O	I/O	I/O
3	I/O	I/O	I/O	41	I/O	I/O	I/O
4	I/O	I/O	I/O	42	I/O	I/O	I/O
5	I/O	I/O	I/O	43	I/O	I/O	I/O
6	I/O	I/O	I/O	44	V _{CCI}	V _{CCI}	V _{CCI}
7	I/O	I/O	I/O	45	I/O	I/O	I/O
8	I/O	I/O	I/O	46	I/O	I/O	I/O
9	TMS	TMS	TMS	47	I/O	I/O	I/O
10	V _{CCI}	V _{CCI}	V _{CCI}	48	I/O	I/O	I/O
11	GND	GND	GND	49	I/O	I/O	I/O
12	I/O	I/O	I/O	50	I/O	I/O	I/O
13	I/O	I/O	I/O	51	I/O	I/O	I/O
14	I/O	I/O	I/O	52	I/O	I/O	I/O
15	I/O	I/O	I/O	53	I/O	I/O	I/O
16	I/O	I/O	I/O	54	PRB, I/O	PRB, I/O	PRB, I/O
17	I/O	I/O	I/O	55	I/O	I/O	I/O
18	I/O	I/O	I/O	56	V _{CCA}	V _{CCA}	V _{CCA}
19	NC	NC	NC	57	GND	GND	GND
20	V _{CCA}	V _{CCA}	V _{CCA}	58	NC	NC	NC
21	I/O	I/O	I/O	59	I/O	I/O	I/O
22	TRST, I/O	TRST, I/O	TRST, I/O	60	HCLK	HCLK	HCLK
23	I/O	I/O	I/O	61	I/O	I/O	I/O
24	I/O	I/O	I/O	62	I/O	I/O	I/O
25	I/O	I/O	I/O	63	I/O	I/O	I/O
26	I/O	I/O	I/O	64	I/O	I/O	I/O
27	I/O	I/O	I/O	65	I/O	I/O	I/O
28	GND	GND	GND	66	I/O	I/O	I/O
29	V _{CCI}	V _{CCI}	V _{CCI}	67	I/O	I/O	I/O
30	V _{CCA}	V _{CCA}	V _{CCA}	68	V _{CCI}	V _{CCI}	V _{CCI}
31	I/O	I/O	I/O	69	I/O	I/O	I/O
32	I/O	I/O	I/O	70	I/O	I/O	I/O
33	I/O	I/O	I/O	71	TDO, I/O	TDO, I/O	TDO, I/O
34	I/O	I/O	I/O	72	I/O	I/O	I/O
35	I/O	I/O	I/O	73	GND	GND	GND
36	GND	GND	GND	74	I/O	I/O	I/O
37	I/O	I/O	I/O	75	I/O	I/O	I/O
38	I/O	I/O	I/O	76	I/O	I/O	I/O

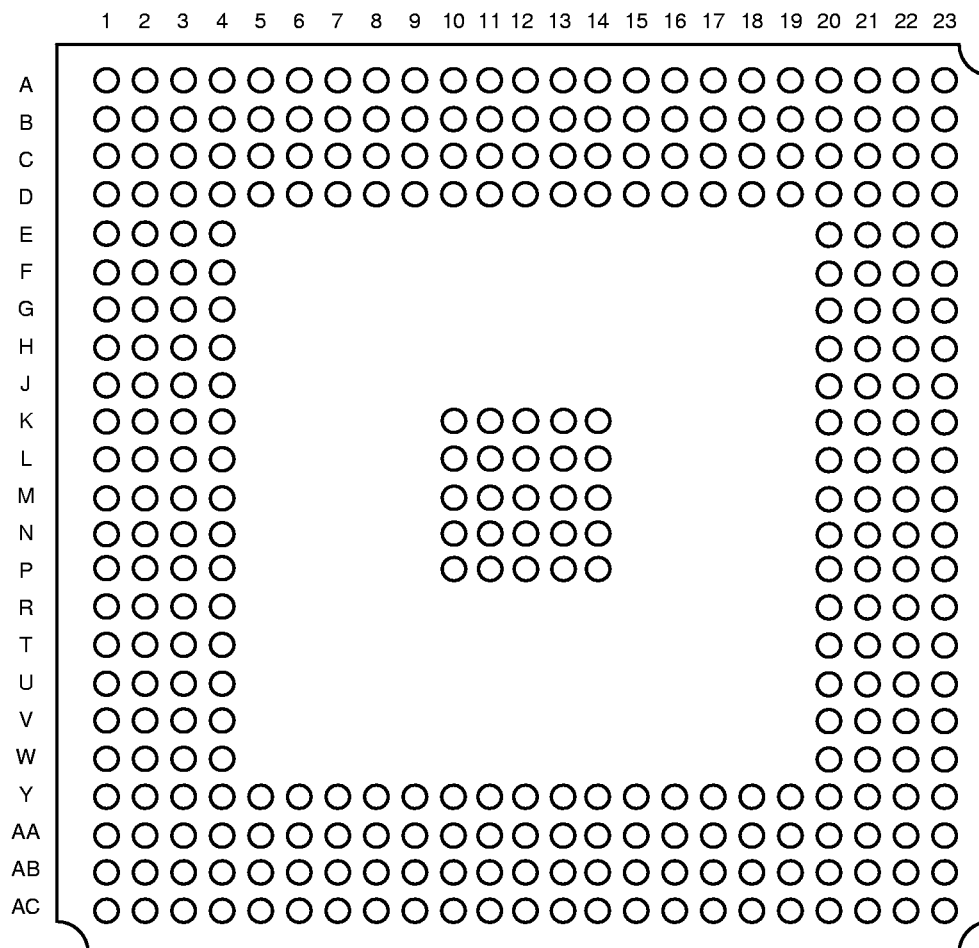
144-Pin TQFP (Continued)

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
77	I/O	I/O	I/O
78	I/O	I/O	I/O
79	V _{CCA}	V _{CCA}	V _{CCA}
80	V _{CCI}	V _{CCI}	V _{CCI}
81	GND	GND	GND
82	I/O	I/O	I/O
83	I/O	I/O	I/O
84	I/O	I/O	I/O
85	I/O	I/O	I/O
86	I/O	I/O	I/O
87	I/O	I/O	I/O
88	I/O	I/O	I/O
89	V _{CCA}	V _{CCA}	V _{CCA}
90	NC	NC	NC
91	I/O	I/O	I/O
92	I/O	I/O	I/O
93	I/O	I/O	I/O
94	I/O	I/O	I/O
95	I/O	I/O	I/O
96	I/O	I/O	I/O
97	I/O	I/O	I/O
98	V _{CCA}	V _{CCA}	V _{CCA}
99	GND	GND	GND
100	I/O	I/O	I/O
101	GND	GND	GND
102	V _{CCI}	V _{CCI}	V _{CCI}
103	I/O	I/O	I/O
104	I/O	I/O	I/O
105	I/O	I/O	I/O
106	I/O	I/O	I/O
107	I/O	I/O	I/O
108	I/O	I/O	I/O
109	GND	GND	GND
110	I/O	I/O	I/O

Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
111	I/O	I/O	I/O
112	I/O	I/O	I/O
113	I/O	I/O	I/O
114	I/O	I/O	I/O
115	V _{CCI}	V _{CCI}	V _{CCI}
116	I/O	I/O	I/O
117	I/O	I/O	I/O
118	I/O	I/O	I/O
119	I/O	I/O	I/O
120	I/O	I/O	I/O
121	I/O	I/O	I/O
122	I/O	I/O	I/O
123	I/O	I/O	I/O
124	I/O	I/O	I/O
125	CLKA	CLKA	CLKA
126	CLKB	CLKB	CLKB
127	NC	NC	NC
128	GND	GND	GND
129	V _{CCA}	V _{CCA}	V _{CCA}
130	I/O	I/O	I/O
131	PRA, I/O	PRA, I/O	PRA, I/O
132	I/O	I/O	I/O
133	I/O	I/O	I/O
134	I/O	I/O	I/O
135	I/O	I/O	I/O
136	I/O	I/O	I/O
137	I/O	I/O	I/O
138	I/O	I/O	I/O
139	I/O	I/O	I/O
140	V _{CCI}	V _{CCI}	V _{CCI}
141	I/O	I/O	I/O
142	I/O	I/O	I/O
143	I/O	I/O	I/O
144	TCK, I/O	TCK, I/O	TCK, I/O

Package Pin Assignments (Continued)

329-Pin PBGA (Top View)



329-Pin PBGA

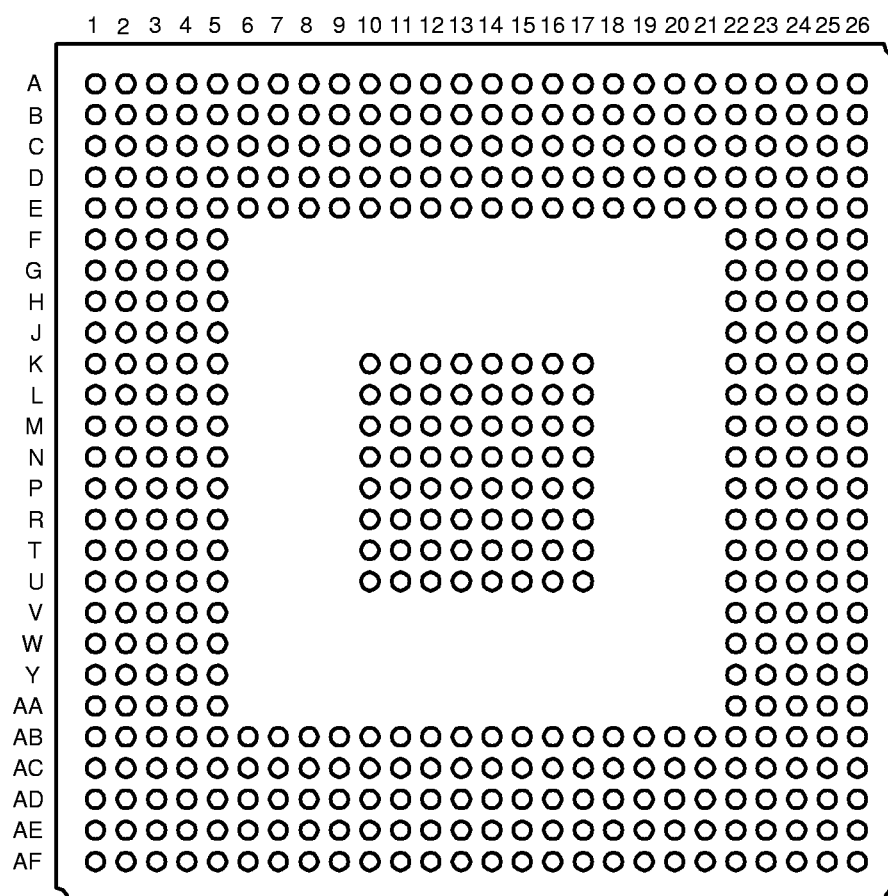
Pin Number	A54SX32 Function	Pin Number	A54SX32 Function	Pin Number	A54SX32 Function	Pin Number	A54SX32 Function
A1	GND	AA23	V _{CCI}	AC22	V _{CCI}	C21	V _{CCI}
A2	GND	AB1	I/O	AC23	GND	C22	GND
A3	V _{CCI}	AB2	GND	B1	V _{CCI}	C23	NC
A4	NC	AB3	I/O	B2	GND	D1	I/O
A5	I/O	AB4	I/O	B3	I/O	D2	I/O
A6	I/O	AB5	I/O	B4	I/O	D3	I/O
A7	V _{CCI}	AB6	I/O	B5	I/O	D4	TCK, I/O
A8	NC	AB7	I/O	B6	I/O	D5	I/O
A9	I/O	AB8	I/O	B7	I/O	D6	I/O
A10	I/O	AB9	I/O	B8	I/O	D7	I/O
A11	I/O	AB10	I/O	B9	I/O	D8	I/O
A12	I/O	AB11	PRB, I/O	B10	I/O	D9	I/O
A13	CLKB	AB12	I/O	B11	I/O	D10	I/O
A14	I/O	AB13	HCLK	B12	PRA, I/O	D11	V _{CCA}
A15	I/O	AB14	I/O	B13	CLKA	D12	NC
A16	I/O	AB15	I/O	B14	I/O	D13	I/O
A17	I/O	AB16	I/O	B15	I/O	D14	I/O
A18	I/O	AB17	I/O	B16	I/O	D15	I/O
A19	I/O	AB18	I/O	B17	I/O	D16	I/O
A20	I/O	AB19	I/O	B18	I/O	D17	I/O
A21	NC	AB20	I/O	B19	I/O	D18	I/O
A22	V _{CCI}	AB21	I/O	B20	I/O	D19	I/O
A23	GND	AB22	GND	B21	I/O	D20	I/O
AA1	V _{CCI}	AB23	I/O	B22	GND	D21	I/O
AA2	I/O	AC1	GND	B23	V _{CCI}	D22	I/O
AA3	GND	AC2	V _{CCI}	C1	NC	D23	I/O
AA4	I/O	AC3	NC	C2	TDI, I/O	E1	V _{CCI}
AA5	I/O	AC4	I/O	C3	GND	E2	I/O
AA6	I/O	AC5	I/O	C4	I/O	E3	I/O
AA7	I/O	AC6	I/O	C5	I/O	E4	I/O
AA8	I/O	AC7	I/O	C6	I/O	E20	I/O
AA9	I/O	AC8	I/O	C7	I/O	E21	I/O
AA10	I/O	AC9	V _{CCI}	C8	I/O	E22	I/O
AA11	I/O	AC10	I/O	C9	I/O	E23	I/O
AA12	I/O	AC11	I/O	C10	I/O	F1	I/O
AA13	I/O	AC12	I/O	C11	I/O	F2	TMS
AA14	I/O	AC13	I/O	C12	I/O	F3	I/O
AA15	I/O	AC14	I/O	C13	I/O	F4	I/O
AA16	I/O	AC15	NC	C14	I/O	F20	I/O
AA17	I/O	AC16	I/O	C15	I/O	F21	I/O
AA18	I/O	AC17	I/O	C16	I/O	F22	I/O
AA19	I/O	AC18	I/O	C17	I/O	F23	I/O
AA20	TDO, I/O	AC19	I/O	C18	I/O	G1	I/O
AA21	V _{CCI}	AC20	I/O	C19	I/O	G2	I/O
AA22	I/O	AC21	NC	C20	I/O	G3	I/O

329-Pin PBGA (Continued)

Pin Number	A54SX32 Function	Pin Number	A54SX32 Function	Pin Number	A54SX32 Function	Pin Number	A54SX32 Function
G4	I/O	L21	I/O	R2	I/O	Y5	I/O
G21	I/O	L22	I/O	R3	I/O	Y6	I/O
G22	I/O	L23	NC	R4	I/O	Y7	I/O
G23	GND	M1	I/O	R20	I/O	Y8	I/O
H1	I/O	M2	I/O	R21	I/O	Y9	I/O
H2	I/O	M3	I/O	R22	I/O	Y10	I/O
H3	I/O	M4	V _{CCA}	R23	I/O	Y11	I/O
H4	I/O	M10	GND	T1	I/O	Y12	V _{CCA}
H20	V _{CCA}	M11	GND	T2	I/O	Y13	NC
H21	I/O	M12	GND	T3	I/O	Y14	I/O
H22	I/O	M13	GND	T4	I/O	Y15	I/O
H23	I/O	M14	GND	T20	I/O	Y16	I/O
J1	NC	M20	V _{CCA}	T21	I/O	Y17	I/O
J2	I/O	M21	I/O	T22	I/O	Y18	I/O
J3	I/O	M22	I/O	T23	I/O	Y19	I/O
J4	I/O	M23	V _{CCI}	U1	I/O	Y20	GND
J20	I/O	N1	I/O	U2	I/O	Y21	I/O
J21	I/O	N2	TRST, I/O	U3	V _{CCA}	Y22	I/O
J22	I/O	N3	I/O	U4	I/O	Y23	I/O
J23	I/O	N4	I/O	U20	I/O		
K1	I/O	N10	GND	U21	V _{CCA}		
K2	I/O	N11	GND	U22	I/O		
K3	I/O	N12	GND	U23	I/O		
K4	I/O	N13	GND	V1	V _{CCI}		
K10	GND	N14	GND	V2	I/O		
K11	GND	N20	NC	V3	I/O		
K12	GND	N21	I/O	V4	I/O		
K13	GND	N22	I/O	V20	I/O		
K14	GND	N23	I/O	V21	I/O		
K20	I/O	P1	I/O	V22	I/O		
K21	I/O	P2	I/O	V23	I/O		
K22	I/O	P3	I/O	W1	I/O		
K23	I/O	P4	I/O	W2	I/O		
L1	I/O	P10	GND	W3	I/O		
L2	I/O	P11	GND	W4	I/O		
L3	I/O	P12	GND	W20	I/O		
L4	NC	P13	GND	W21	I/O		
L10	GND	P14	GND	W22	I/O		
L11	GND	P20	I/O	W23	NC		
L12	GND	P21	I/O	Y1	NC		
L13	GND	P22	I/O	Y2	I/O		
L14	GND	P23	I/O	Y3	I/O		
L20	NC	R1	I/O	Y4	GND		

Package Pin Assignments (Continued)

484-Pin FBGA (Top View)



484-Pin FBGA

Pin Number	A54SX72A Function	Pin Number	A54SX72A Function	Pin Number	A54SX72A Function	Pin Number	A54SX72A Function
A1	NC	AB11	I/O	AD5	I/O	AE25	NC
A2	NC	AB12	PRB, I/O	AD6	I/O	AE26	NC
A3	I/O	AB13	V _{CCA}	AD7	I/O	AF1	NC
A4	I/O	AB14	I/O	AD8	I/O	AF2	NC
A5	I/O	AB15	I/O	AD9	V _{CCI}	AF3	I/O
A6	I/O	AB16	I/O	AD10	I/O	AF4	I/O
A7	I/O	AB17	I/O	AD11	I/O	AF5	I/O
A8	I/O	AB18	I/O	AD12	I/O	AF6	I/O
A9	I/O	AB19	I/O	AD13	V _{CCI}	AF7	I/O
A10	I/O	AB20	TDO, I/O	AD14	I/O	AF8	I/O
A11	I/O	AB21	GND	AD15	I/O	AF9	I/O
A12	I/O	AB22	I/O	AD16	I/O	AF10	I/O
A13	I/O	AB23	I/O	AD17	V _{CCI}	AF11	I/O
A14	NC	AB24	I/O	AD18	I/O	AF12	NC
A15	I/O	AB25	I/O	AD19	I/O	AF13	HCLK
A16	I/O	AB26	I/O	AD20	I/O	AF14	QCLKB
A17	I/O	AC1	I/O	AD21	I/O	AF15	I/O
A18	I/O	AC2	I/O	AD22	I/O	AF16	I/O
A19	I/O	AC3	I/O	AD23	V _{CCI}	AF17	I/O
A20	I/O	AC4	I/O	AD24	I/O	AF18	I/O
A21	I/O	AC5	V _{CCI}	AD25	I/O	AF19	I/O
A22	I/O	AC6	I/O	AD26	I/O	AF20	I/O
A23	I/O	AC7	V _{CCI}	AE1	NC	AF21	I/O
A24	I/O	AC8	I/O	AE2	I/O	AF22	I/O
A25	NC	AC9	I/O	AE3	I/O	AF23	I/O
A26	NC	AC10	I/O	AE4	I/O	AF24	I/O
AA1	I/O	AC11	I/O	AE5	I/O	AF25	NC
AA2	I/O	AC12	QCLKA	AE6	I/O	AF26	NC
AA3	V _{CCA}	AC13	I/O	AE7	I/O	B1	NC
AA4	I/O	AC14	I/O	AE8	I/O	B2	NC
AA5	I/O	AC15	I/O	AE9	I/O	B3	I/O
AA22	I/O	AC16	I/O	AE10	I/O	B4	I/O
AA23	I/O	AC17	I/O	AE11	I/O	B5	I/O
AA24	I/O	AC18	I/O	AE12	I/O	B6	I/O
AA25	I/O	AC19	I/O	AE13	I/O	B7	I/O
AA26	I/O	AC20	V _{CCI}	AE14	I/O	B8	I/O
AB1	NC	AC21	I/O	AE15	I/O	B9	I/O
AB2	V _{CCI}	AC22	I/O	AE16	I/O	B10	I/O
AB3	I/O	AC23	I/O	AE17	I/O	B11	I/O
AB4	I/O	AC24	I/O	AE18	I/O	B12	I/O
AB5	I/O	AC25	I/O	AE19	I/O	B13	V _{CCI}
AB6	I/O	AC26	I/O	AE20	I/O	B14	CLKA
AB7	I/O	AD1	I/O	AE21	I/O	B15	I/O
AB8	I/O	AD2	I/O	AE22	I/O	B16	I/O
AB9	I/O	AD3	GND	AE23	I/O	B17	I/O
AB10	I/O	AD4	I/O	AE24	I/O	B18	V _{CCI}

Note: NC denotes No Connection.

484-Pin FBGA (Continued)

Pin Number	A54SX72A Function	Pin Number	A54SX72A Function	Pin Number	A54SX72A Function	Pin Number	A54SX72A Function
B19	I/O	D13	I/O	F23	I/O	K17	GND
B20	I/O	D14	I/O	F24	I/O	K22	I/O
B21	I/O	D15	I/O	F25	I/O	K23	I/O
B22	I/O	D16	I/O	F26	I/O	K24	NC
B23	I/O	D17	I/O	G1	I/O	K25	I/O
B24	I/O	D18	I/O	G2	I/O	K26	I/O
B25	I/O	D19	I/O	G3	I/O	L1	I/O
B26	NC	D20	I/O	G4	I/O	L2	I/O
C1	I/O	D21	V _{CCI}	G5	I/O	L3	I/O
C2	I/O	D22	GND	G22	I/O	L4	I/O
C3	I/O	D23	I/O	G23	V _{CCA}	L5	I/O
C4	I/O	D24	I/O	G24	I/O	L10	GND
C5	I/O	D25	I/O	G25	I/O	L11	GND
C6	V _{CCI}	D26	I/O	G26	I/O	L12	GND
C7	I/O	E1	I/O	H1	I/O	L13	GND
C8	I/O	E2	I/O	H2	I/O	L14	GND
C9	V _{CCI}	E3	I/O	H3	I/O	L15	GND
C10	I/O	E4	I/O	H4	I/O	L16	GND
C11	I/O	E5	GND	H5	I/O	L17	GND
C12	I/O	E6	TDI, IO	H22	I/O	L22	I/O
C13	PRA, I/O	E7	I/O	H23	I/O	L23	I/O
C14	I/O	E8	I/O	H24	I/O	L24	I/O
C15	QCLKD	E9	I/O	H25	I/O	L25	I/O
C16	I/O	E10	I/O	H26	I/O	L26	I/O
C17	I/O	E11	I/O	J1	I/O	M1	NC
C18	I/O	E12	I/O	J2	I/O	M2	I/O
C19	I/O	E13	V _{CCA}	J3	I/O	M3	I/O
C20	V _{CCI}	E14	CLKB	J4	I/O	M4	I/O
C21	I/O	E15	I/O	J5	I/O	M5	I/O
C22	I/O	E16	I/O	J22	I/O	M10	GND
C23	I/O	E17	I/O	J23	I/O	M11	GND
C24	I/O	E18	I/O	J24	I/O	M12	GND
C25	I/O	E19	I/O	J25	V _{CCI}	M13	GND
C26	I/O	E20	I/O	J26	I/O	M14	GND
D1	I/O	E21	I/O	K1	I/O	M15	GND
D2	TMS	E22	I/O	K2	V _{CCI}	M16	GND
D3	I/O	E23	I/O	K3	I/O	M17	GND
D4	V _{CCI}	E24	I/O	K4	I/O	M22	I/O
D5	I/O	E25	V _{CCI}	K5	V _{CCA}	M23	I/O
D6	TCK, I/O	E26	GND	K10	GND	M24	I/O
D7	I/O	F1	V _{CCI}	K11	GND	M25	I/O
D8	I/O	F2	I/O	K12	GND	M26	I/O
D9	I/O	F3	I/O	K13	GND	N1	I/O
D10	I/O	F4	I/O	K14	GND	N2	V _{CCI}
D11	I/O	F5	I/O	K15	GND	N3	I/O
D12	QCLKC	F22	I/O	K16	GND	N4	I/O

Note: NC denotes No Connection.

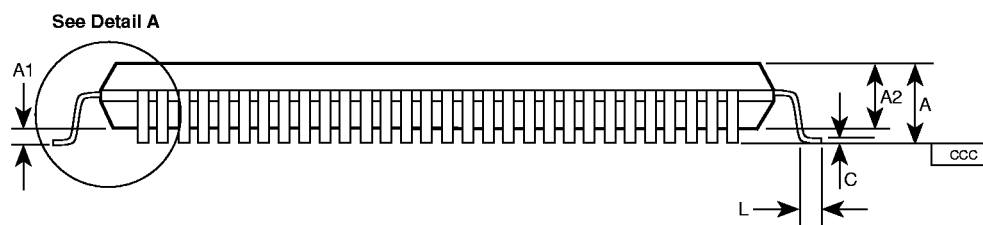
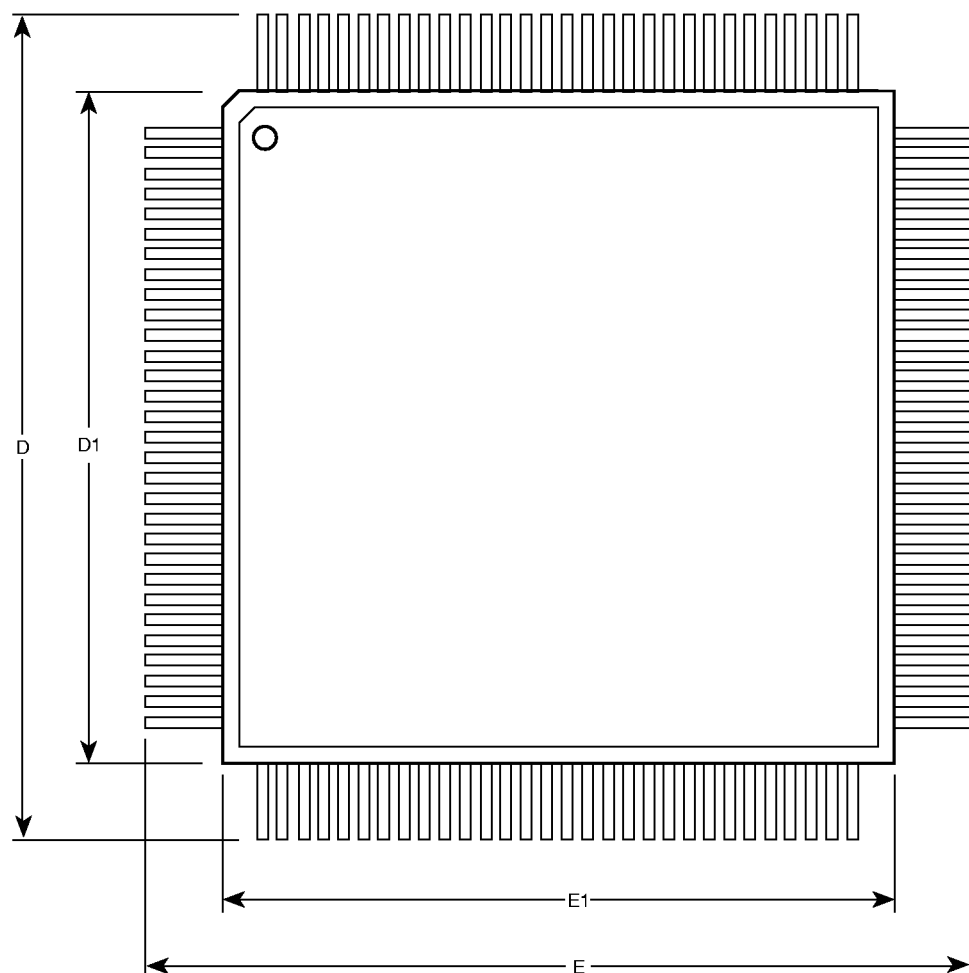
484-Pin FBGA (Continued)

Pin Number	A54SX72A Function	Pin Number	A54SX72A Function	Pin Number	A54SX72A Function	Pin Number	A54SX72A Function
N5	I/O	P24	V _{CCI}	T13	GND	V2	I/O
N10	GND	P25	I/O	T14	GND	V3	I/O
N11	GND	P26	I/O	T15	GND	V4	I/O
N12	GND	R1	I/O	T16	GND	V5	I/O
N13	GND	R2	I/O	T17	GND	V22	V _{CCA}
N14	GND	R3	I/O	T22	I/O	V23	I/O
N15	GND	R4	I/O	T23	I/O	V24	I/O
N16	GND	R5	TRST, I/O	T24	I/O	V25	I/O
N17	GND	R10	GND	T25	I/O	V26	I/O
N22	V _{CCA}	R11	GND	T26	I/O	W1	I/O
N23	I/O	R12	GND	U1	I/O	W2	I/O
N24	I/O	R13	GND	U2	V _{CCI}	W3	I/O
N25	I/O	R14	GND	U3	I/O	W4	I/O
N26	NC	R15	GND	U4	I/O	W5	I/O
P1	I/O	R16	GND	U5	I/O	W22	I/O
P2	I/O	R17	GND	U10	GND	W23	V _{CCA}
P3	I/O	R22	I/O	U11	GND	W24	I/O
P4	I/O	R23	I/O	U12	GND	W25	I/O
P5	V _{CCA}	R24	I/O	U13	GND	W26	I/O
P10	GND	R25	I/O	U14	GND	Y1	I/O
P11	GND	R26	I/O	U15	GND	Y2	I/O
P12	GND	T1	I/O	U16	GND	Y3	I/O
P13	GND	T2	I/O	U17	GND	Y4	I/O
P14	GND	T3	I/O	U22	I/O	Y5	I/O
P15	GND	T4	I/O	U23	I/O	Y22	I/O
P16	GND	T5	I/O	U24	I/O	Y23	I/O
P17	GND	T10	GND	U25	V _{CCI}	Y24	V _{CCI}
P22	I/O	T11	GND	U26	I/O	Y25	I/O
P23	I/O	T12	GND	V1	I/O	Y26	I/O

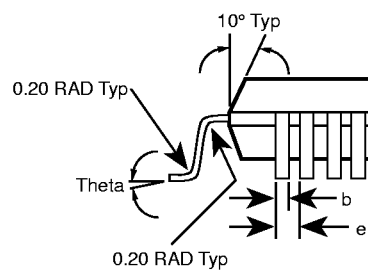
Note: NC denotes No Connection.

Package Mechanical Drawings (Continued)

Plastic Quad Flatpack (PQFP, TQFP)



Detail A



Plastic Quad Flatpack (PQFP)

Jedec Equivalent	PQFP 208 MO-143		
Dimension	Min	Nom	Max
A		3.70	4.10
A1	0.25	0.38	
A2	3.20	3.40	3.60
b	0.17		0.27
c	0.09		0.20
D/E	30.25	30.60	30.85
D1/E1	27.90	28.00	28.10
e	0.50 BSC		
L	0.50	0.60	0.75
ccc			0.10
Theta	0		7 deg
Diameter	19.82	20.32	20.82

Thin Quad Flatpack (TQFP)

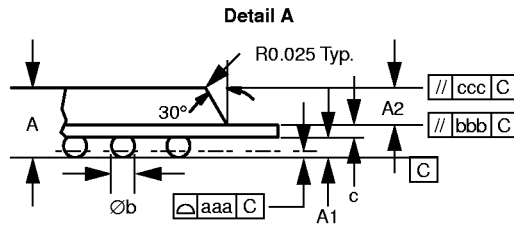
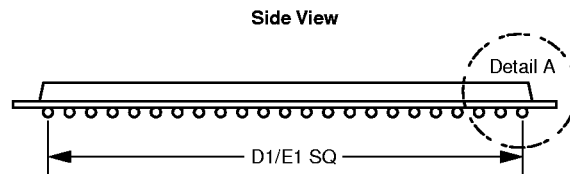
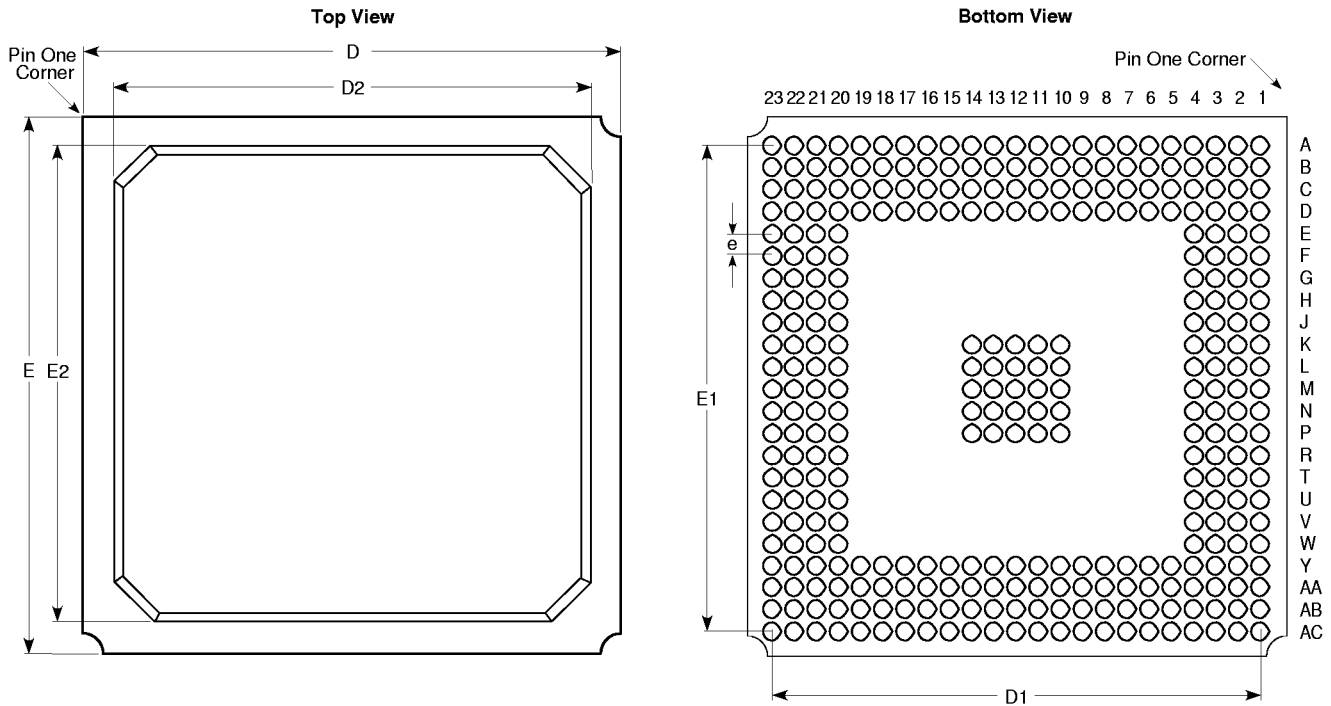
Jedec Equivalent	TQFP 100 MO-136			TQFP 144 MO-136		
Dimension	Min	Nom	Max	Min	Nom	Max
A			1.60			1.60
A1	0.05	0.10	0.15	0.05	0.10	0.15
A2	1.35	1.40	1.45	1.35	1.40	1.45
b	0.17		0.27	0.17		0.27
c	0.09		0.20	0.09		0.20
D/E	15.75	16.00	16.25	21.75	22.00	22.25
D1/E1	13.90	14.00	14.10	19.90	20.00	20.10
e	0.50 BSC			0.50 BSC		
L	0.45	0.60	0.75	0.45	0.60	0.75
ccc			0.10			0.10
Theta	0		7 deg	0		7 deg

Notes:

1. All dimensions are in millimeters.
2. BSC—Basic Spacing between Centers.

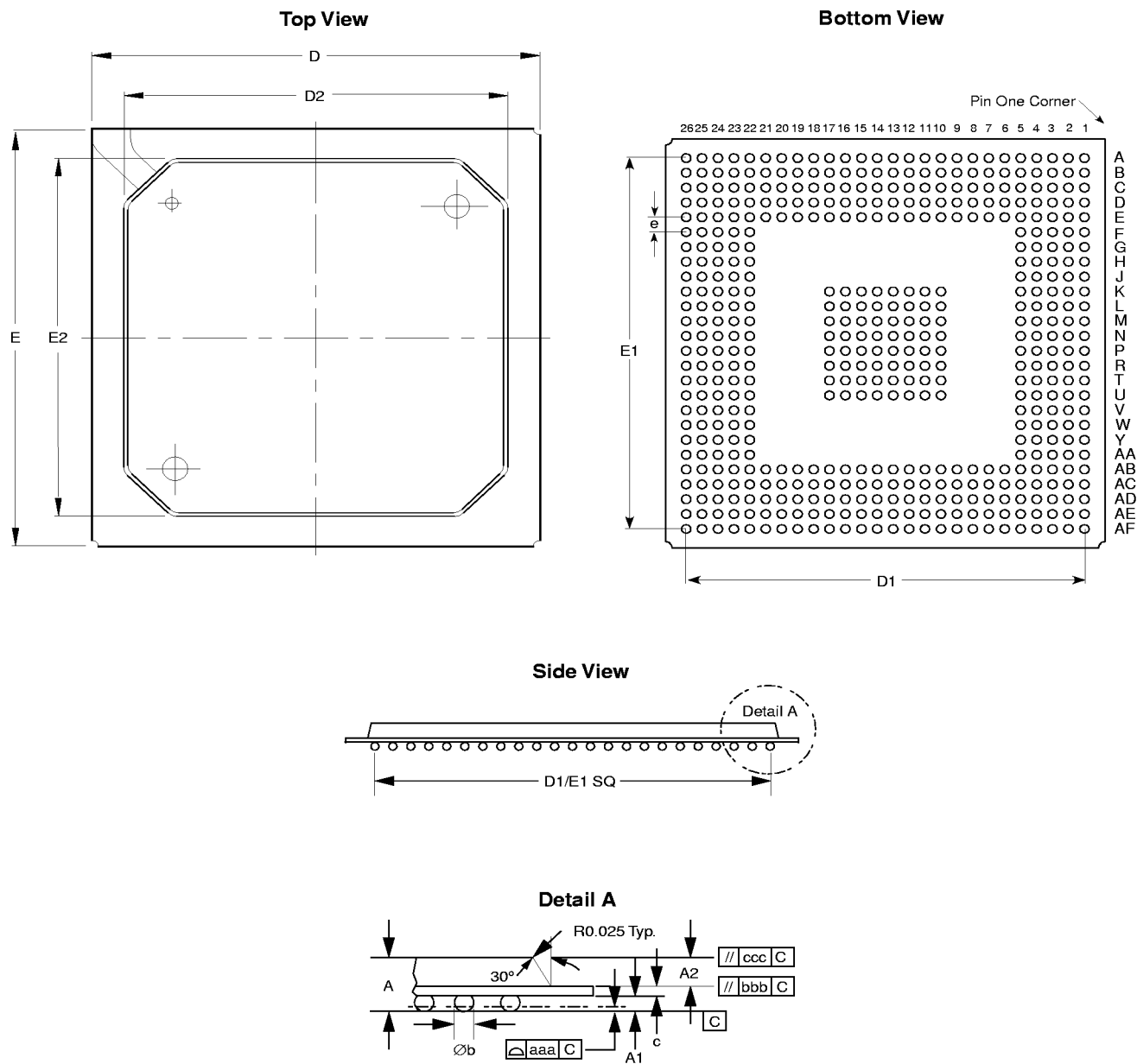
Package Mechanical Drawings (Continued)

Plastic Ball Grid Array (PBGA329)



Package Mechanical Drawing (Continued)

Fine Pitch Ball Grid Array (FBGA 484)



Plastic Ball Grid Array (PBGA)

JEDEC Equivalent	PBGA329			FBGA484		
Dimension	Min.	Nom.	Max.	Min.	Nom.	Max.
A	2.17	2.33	2.70	2.03	2.23	2.43
A1	0.50	0.60	0.70	0.40	0.50	0.60
A2	1.10	1.20	1.30	1.12	1.17	1.22
aaa			0.20			0.15
b	0.60	0.76	0.90	0.50	0.60	0.70
bbb			0.20			0.20
c	0.53	0.60	0.70	0.51	0.56	0.61
ccc			0.25			0.25
D	30.80	31.00	31.20	26.80	27.00	27.20
D1	27.94 BSC			25.00 BSC		
D2	27.90	28.00	28.10	23.80	24.00	24.20
E	30.80	31.00	31.20	26.80	27.00	27.20
E1	27.94 BSC			25.00 BSC		
E2	27.90	28.00	28.10	23.80	24.00	24.20
e	1.27 typ.			1.00 typ.		

Notes:

1. All dimensions are in millimeters.
2. BSC—Basic Spacing between Centers.